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(54) **INTERACTIVE SYSTEM FOR GUIDING ELECTRONICS DESIGN AND ASSEMBLY**

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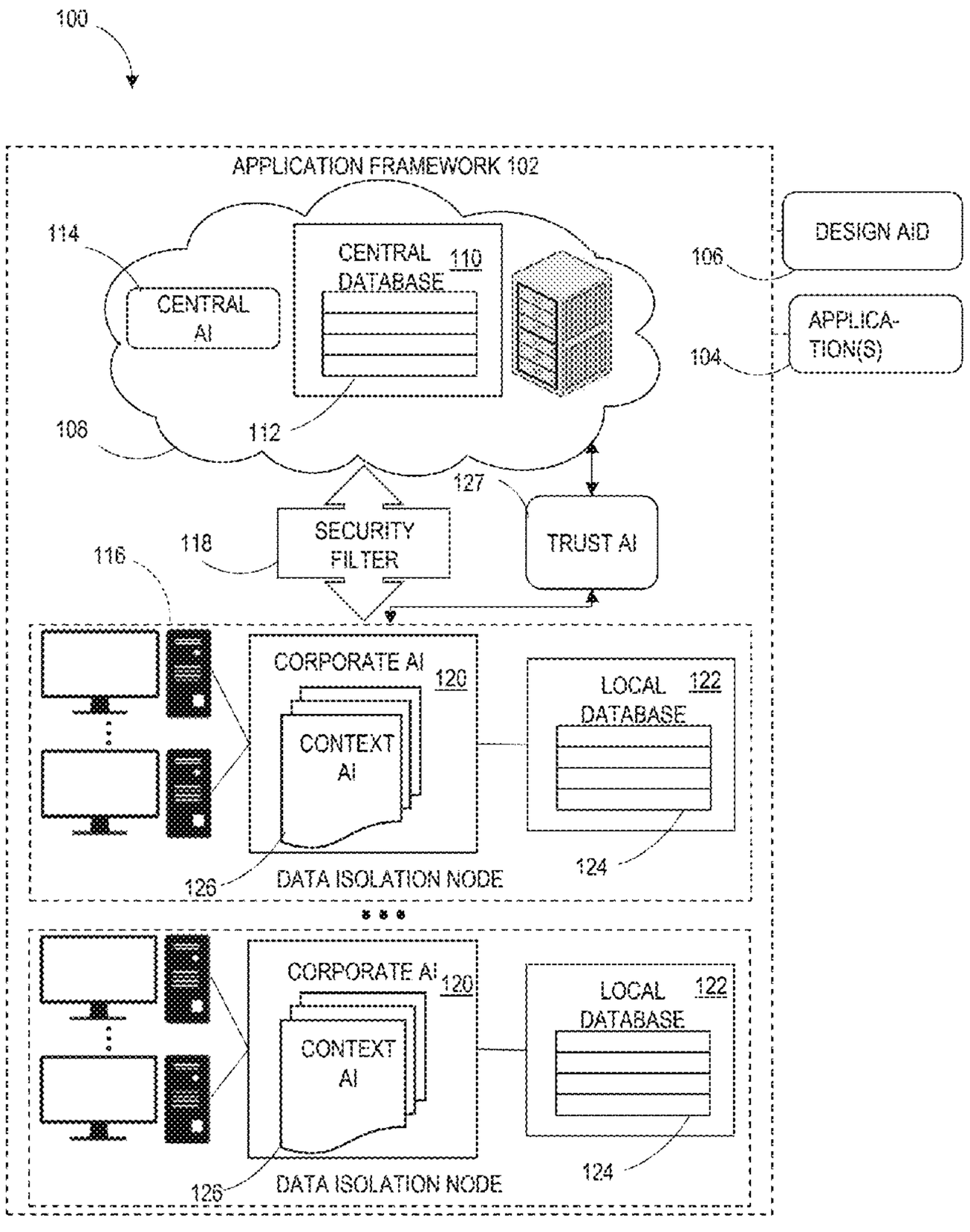
CPC ***G06F 30/31*** (2020.01); *G06F 2115/12* (2020.01)

(57) **ABSTRACT**

A computer implemented method is disclosed relating to the design of electronic circuits and systems. In some examples, a graphical user interface is utilized to receive first information relating to a requested electronic circuit. The first information includes a selected type of electronic circuit and one or more operating criteria relating to requested fundamental functionality of the selected type of electronic circuit. Second information is also received, relating to requested secondary attributes of a hypothetical candidate electronic circuit that satisfies the first information. In response, a set of candidate circuit architectures are displayed satisfying the first information, as well as a visualization of how each of the candidate circuit architectures relates to the second information.



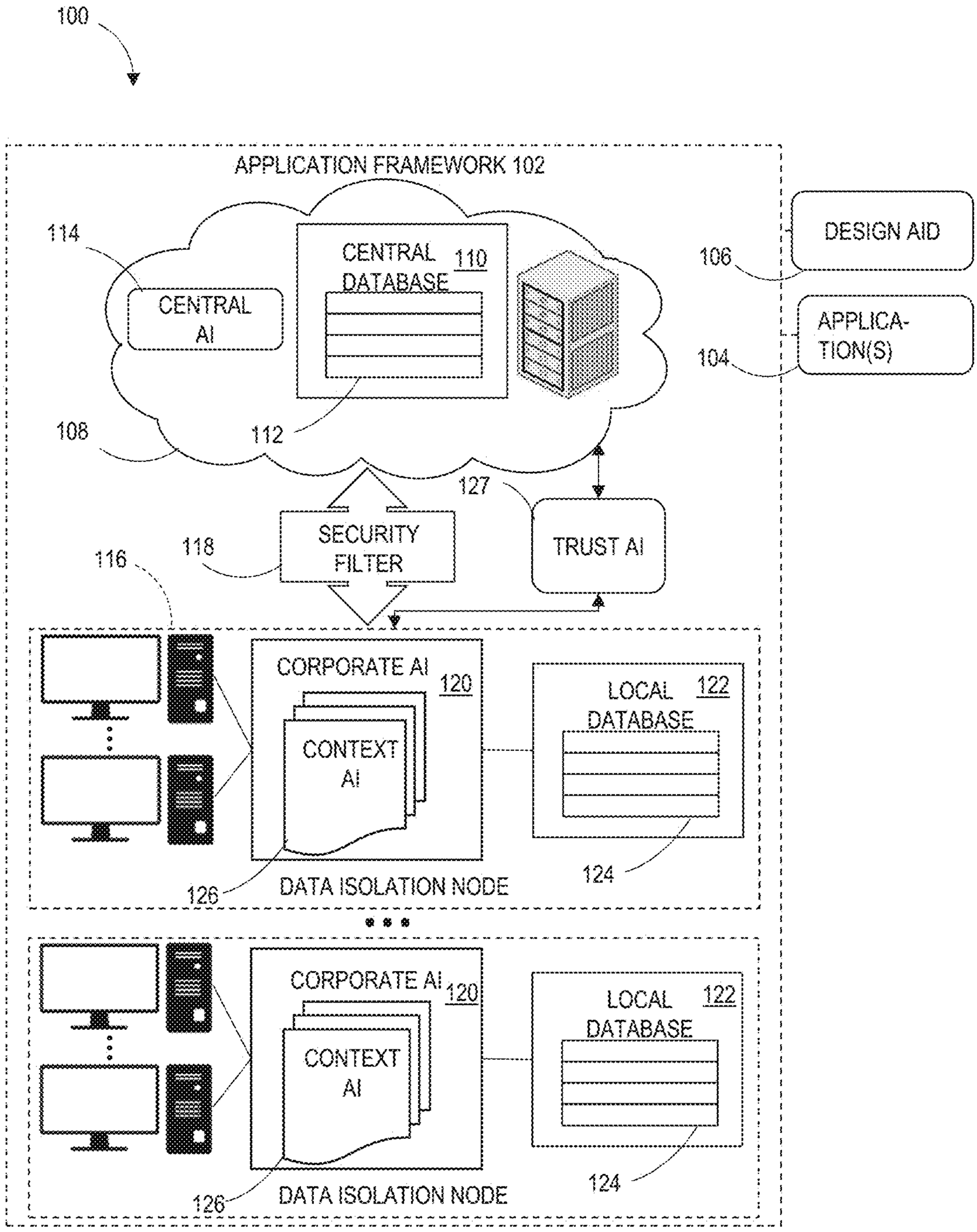

100
APPLICATION FRAMEWORK 102
114
CENTRAL AI
CENTRAL DATABASE 110
108
112
DESIGN AID
106
APPLICA-TION(S)
104
127
TRUST AI
SECURITY FILTER
118
116
CORPORATE AI 120
CONTEXT AI
LOCAL DATABASE 122
124
126
DATA ISOLATION NODE
CORPORATE AI 120
CONTEXT AI
LOCAL DATABASE 122
124
126
DATA ISOLATION NODE

FIG. 1

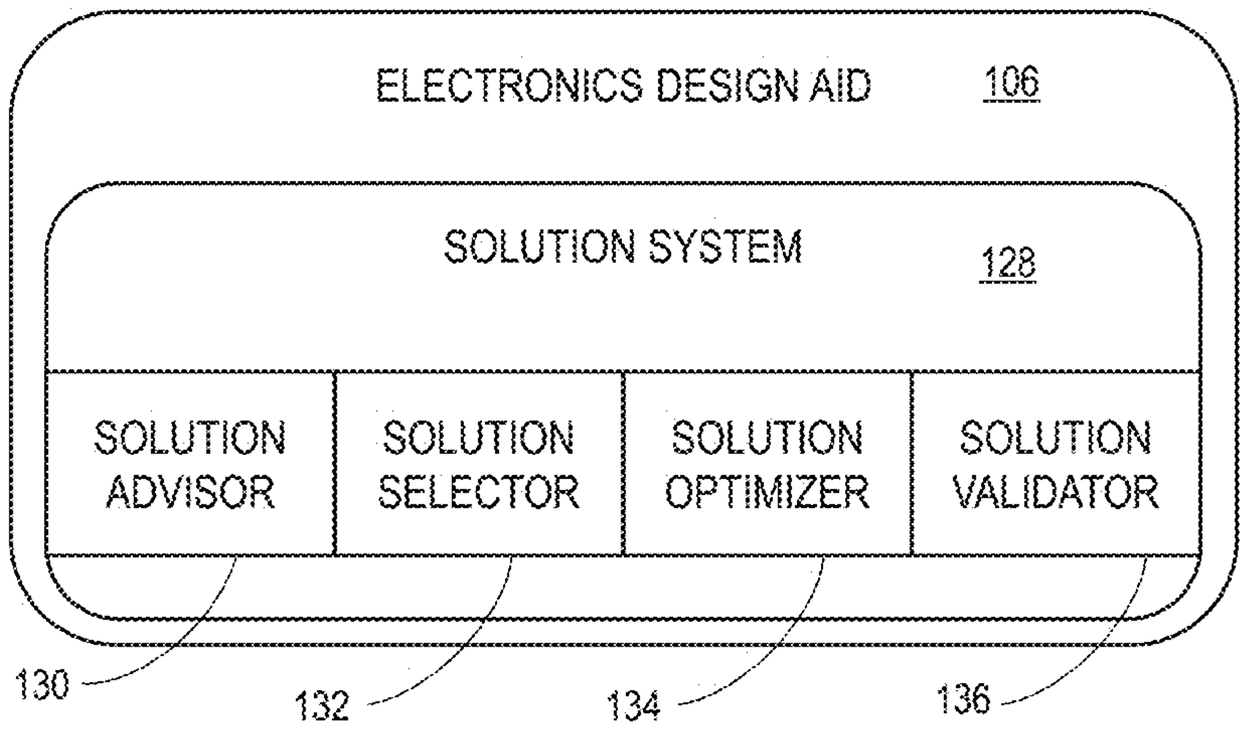

ELECTRONICS DESIGN AID
106
SOLUTION SYSTEM
128
SOLUTION ADVISOR
SOLUTION SELECTOR
SOLUTION OPTIMIZER
SOLUTION VALIDATOR
130
132
134
136

FIG. 2

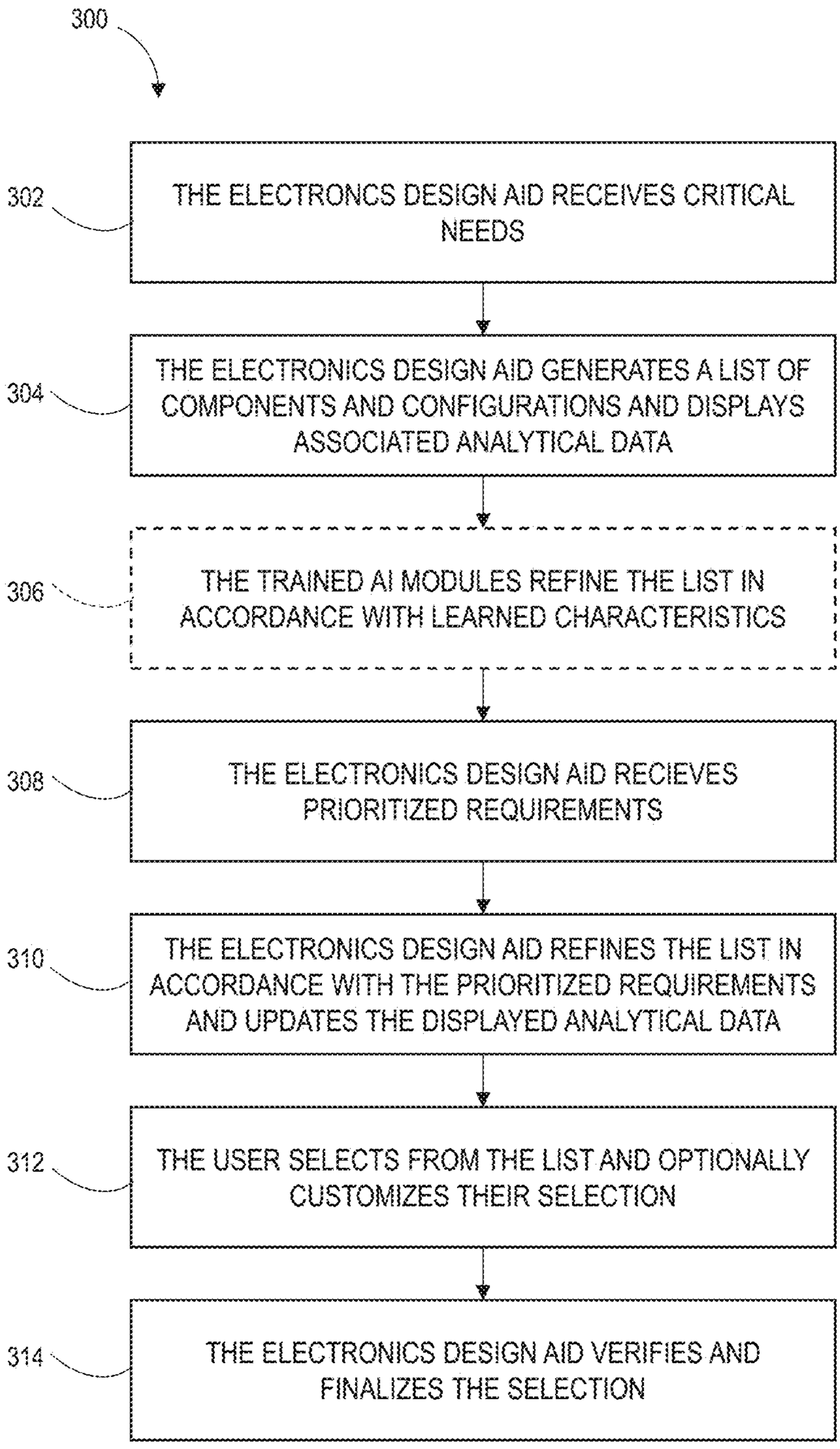

300
302
THE ELECTRONCS DESIGN AID RECEIVES CRITICAL NEEDS
304
THE ELECTRONICS DESIGN AID GENERATES A LIST OF COMPONENTS AND CONFIGURATIONS AND DISPLAYS ASSOCIATED ANALYTICAL DATA
306
THE TRAINED AI MODULES REFINE THE LIST IN ACCORDANCE WITH LEARNED CHARACTERISTICS
308
THE ELECTRONICS DESIGN AID RECIEVES PRIORITIZED REQUIREMENTS
310
THE ELECTRONICS DESIGN AID REFINES THE LIST IN ACCORDANCE WITH THE PRIORITIZED REQUIREMENTS AND UPDATES THE DISPLAYED ANALYTICAL DATA
312
THE USER SELECTS FROM THE LIST AND OPTIONALLY CUSTOMIZES THEIR SELECTION
314
THE ELECTRONICS DESIGN AID VERIFIES AND FINALIZES THE SELECTION

FIG. 3

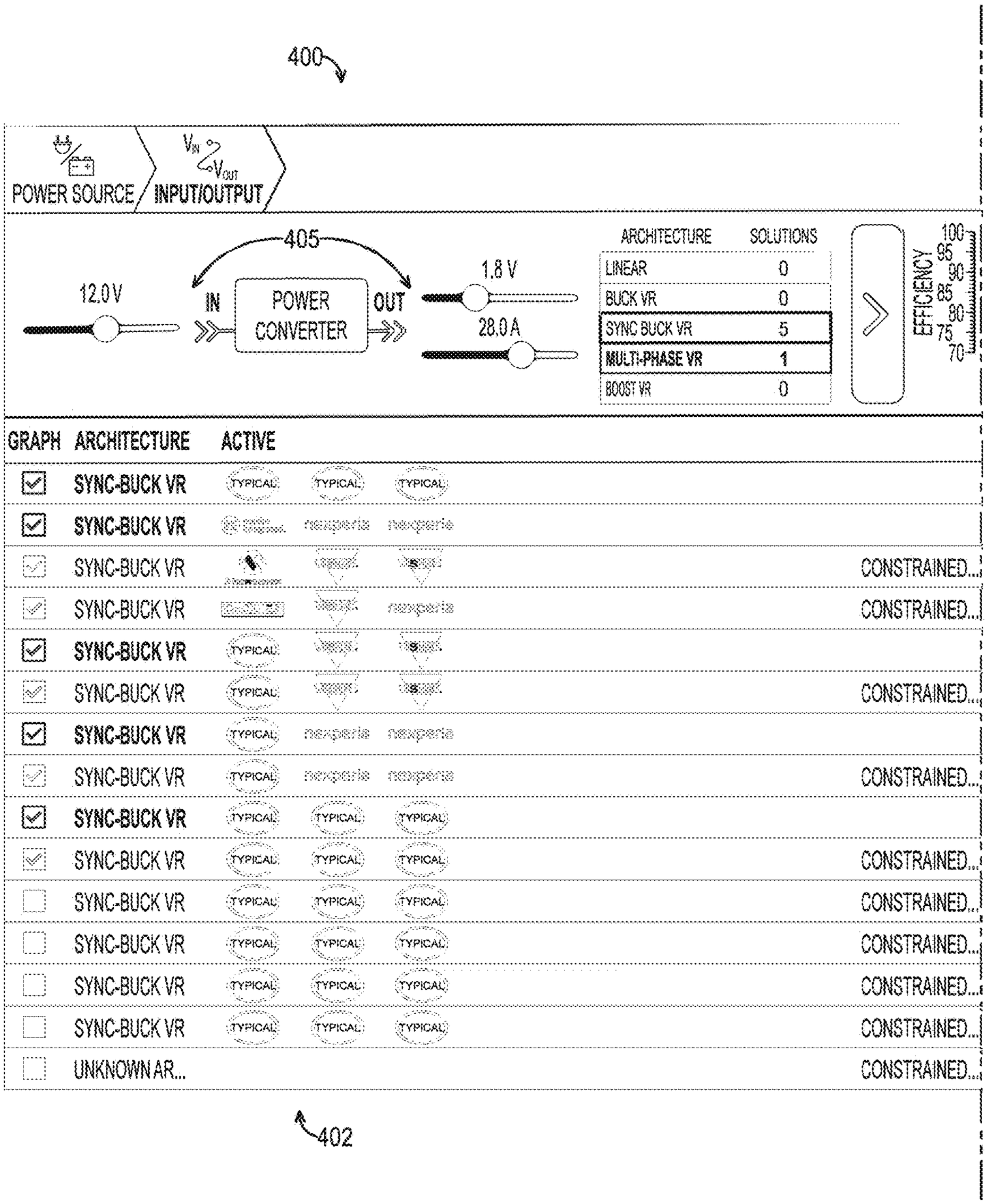

400
POWER SOURCE
INPUT/OUTPUT
V_{IN}
V_{OUT}
405
12.0 V
IN
POWER CONVERTER
OUT
1.8 V
28.0 A
ARCHITECTURE
SOLUTIONS
LINEAR 0
BUCK VR 0
SYNC BUCK VR 5
MULTI-PHASE VR 1
BOOST VR 0
EFFICIENCY
100
95
90
85
80
75
70
GRAPH
ARCHITECTURE
ACTIVE
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
SYNC-BUCK VR
UNKNOWN AR...
TYPICAL
CONSTRAINED...
402

FIG. 4A

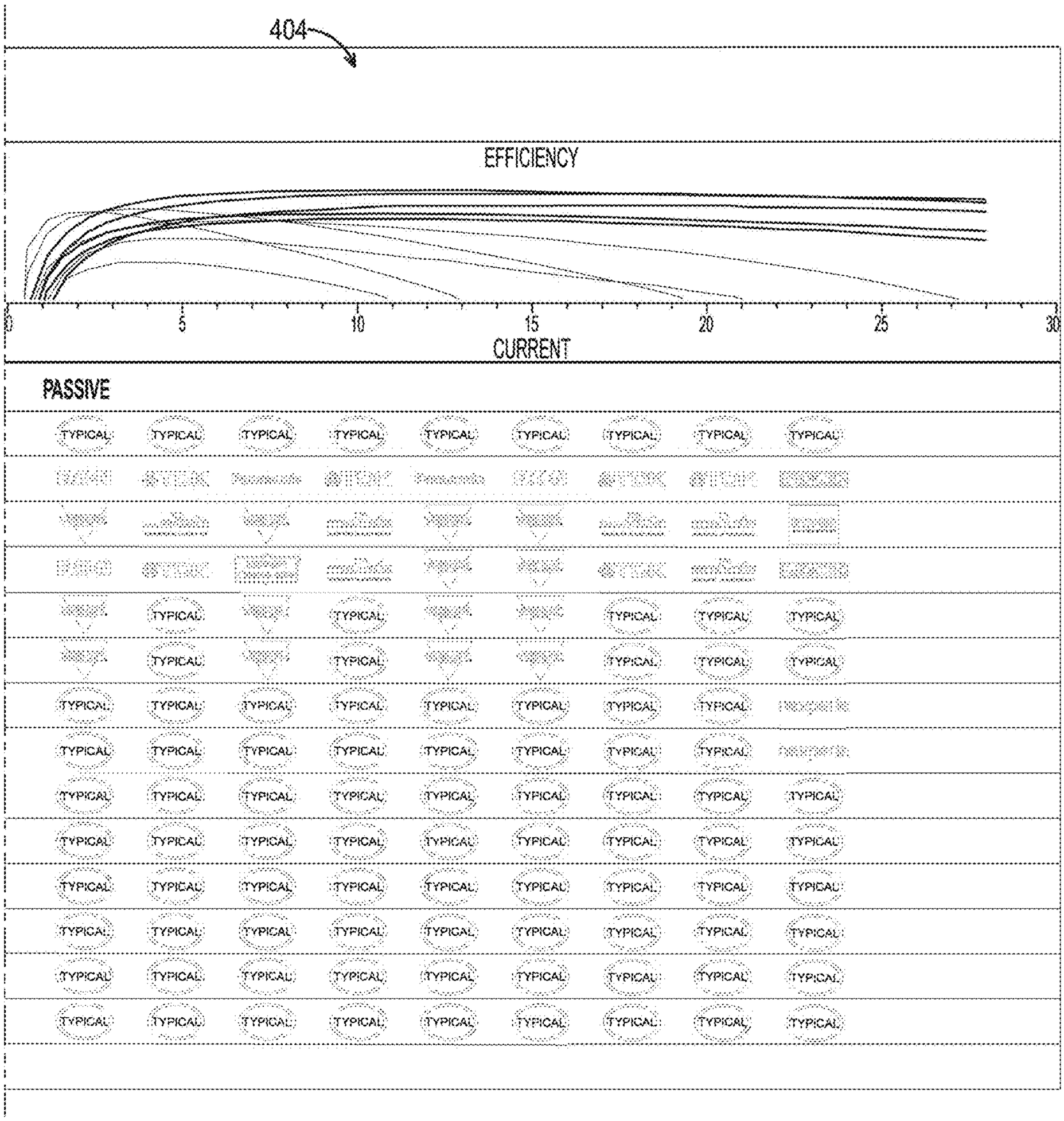


FIG. 4B

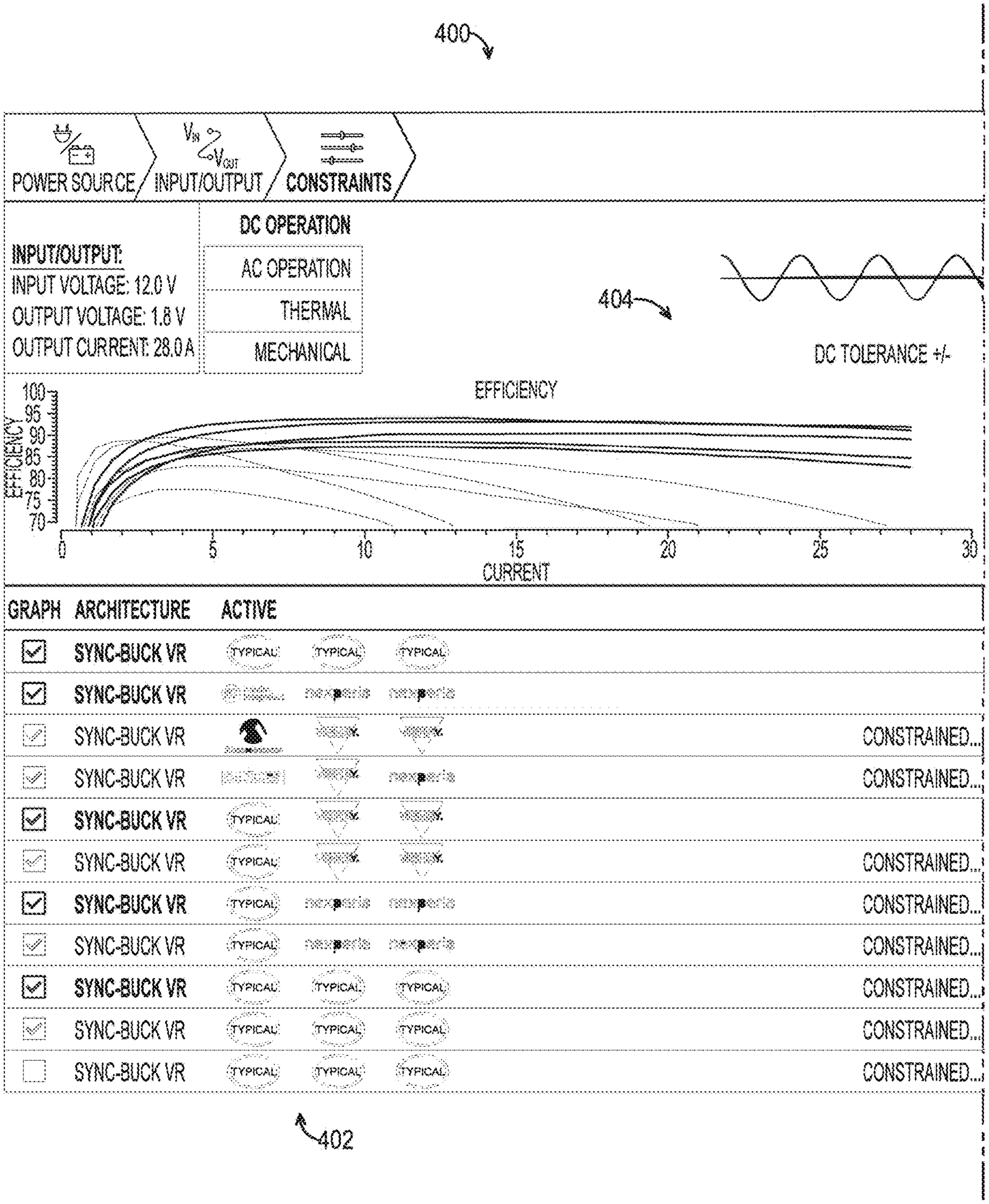

400
POWER SOURCE
INPUT/OUTPUT
CONSTRAINTS
INPUT/OUTPUT:
INPUT VOLTAGE: 12.0 V
OUTPUT VOLTAGE: 1.8 V
OUTPUT CURRENT: 28.0 A
DC OPERATION
AC OPERATION
THERMAL
MECHANICAL
404
DC TOLERANCE +/-
EFFICIENCY
EFFICIENCY
100
95
90
85
80
75
70
0
5
10
15
20
25
30
CURRENT
GRAPH
ARCHITECTURE
ACTIVE
SYNC-BUCK VR
TYPICAL
CONSTRAINED...
402

FIG. 5A

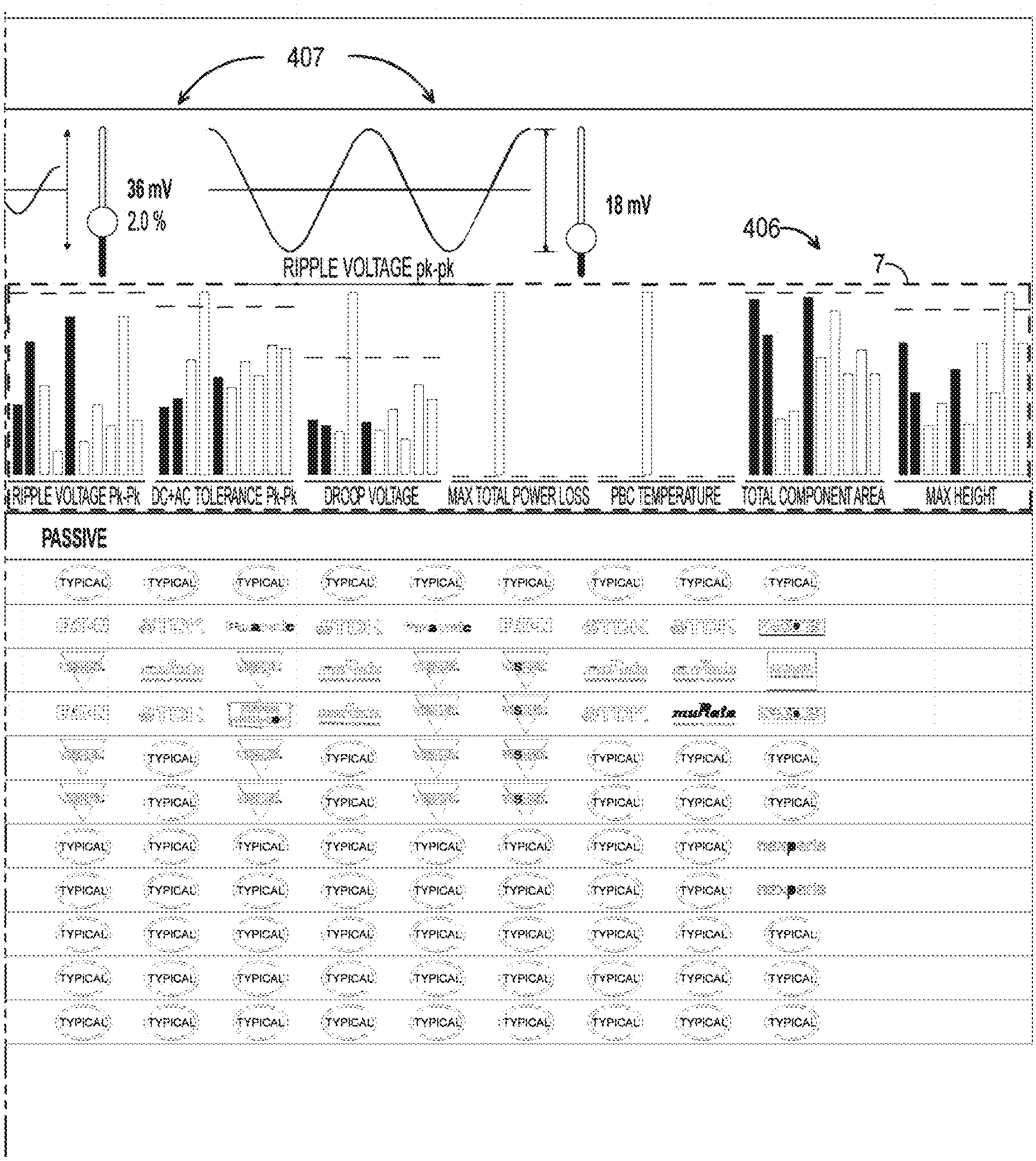

407
36 mV
2.0 %
18 mV
406
RIPPLE VOLTAGE pk-pk
7
RIPPLE VOLTAGE Pk-Pk
DC+AC TOLERANCE Pk-Pk
DROOP VOLTAGE
MAX TOTAL POWER LOSS
PBC TEMPERATURE
TOTAL COMPONENT AREA
MAX HEIGHT
PASSIVE
TYPICAL

FIG. 5B

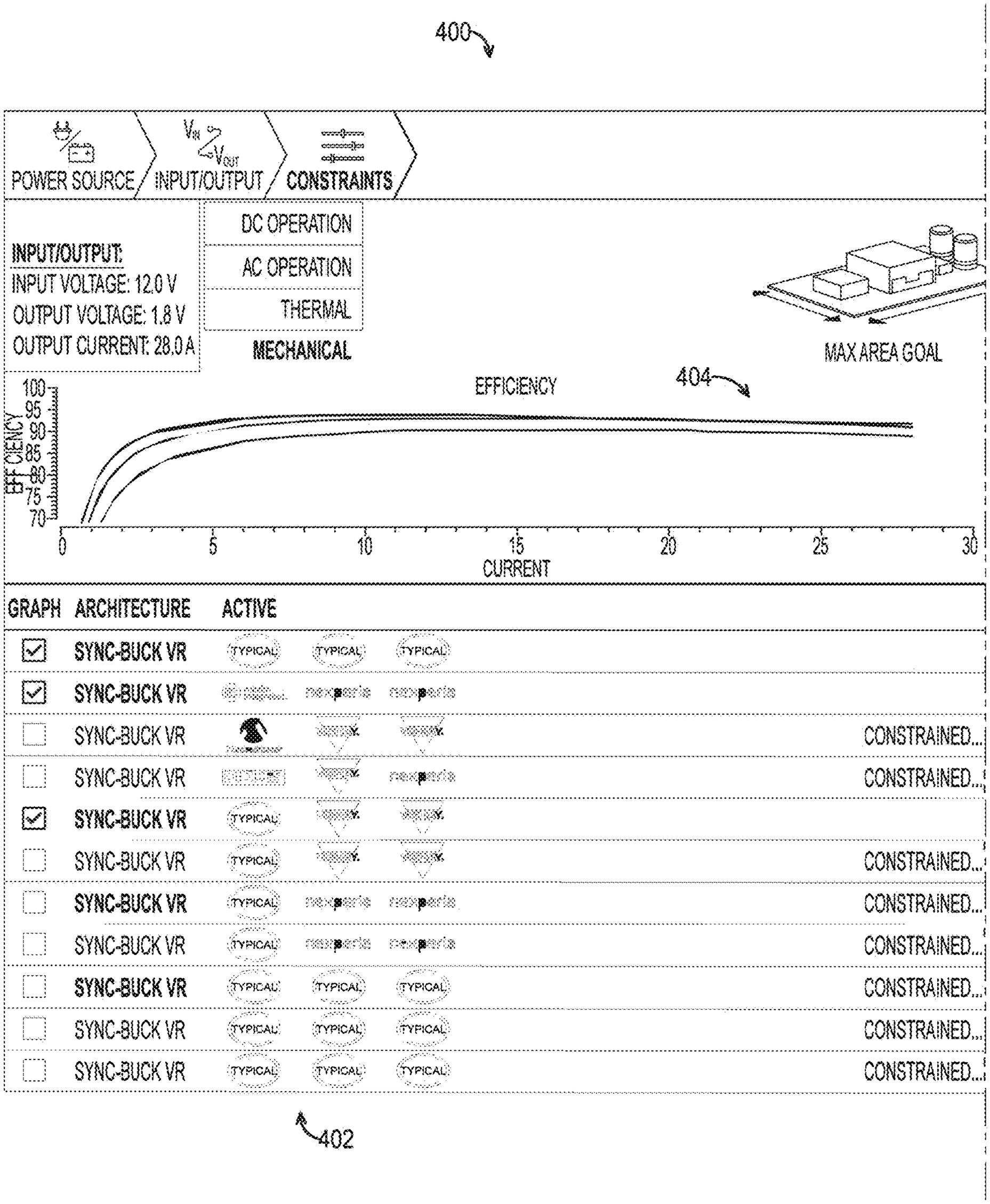

400
POWER SOURCE
INPUT/OUTPUT
CONSTRAINTS
INPUT/OUTPUT:
INPUT VOLTAGE: 12.0 V
OUTPUT VOLTAGE: 1.8 V
OUTPUT CURRENT: 28.0 A
DC OPERATION
AC OPERATION
THERMAL
MECHANICAL
MAX AREA GOAL
404
EFFICIENCY
EFFICIENCY
100
95
90
85
80
75
70
0
5
10
15
20
25
30
CURRENT
GRAPH
ARCHITECTURE
ACTIVE
SYNC-BUCK VR
TYPICAL
CONSTRAINED...
402

FIG. 6A

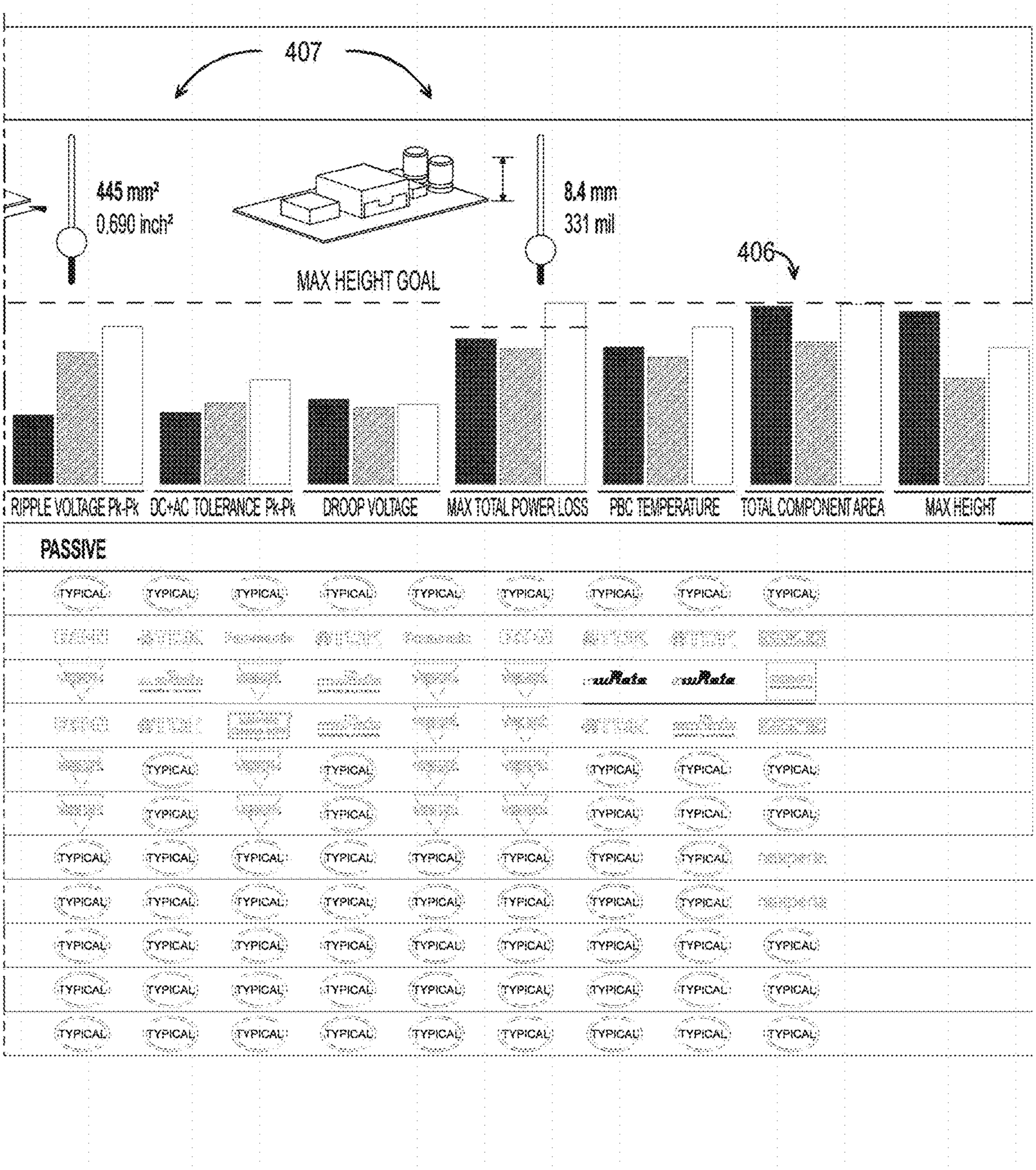

407
445 mm²
0.690 inch²
8.4 mm
331 mil
MAX HEIGHT GOAL
406
RIPPLE VOLTAGE Pk-Pk
DC+AC TOLERANCE Pk-Pk
DROOP VOLTAGE
MAX TOTAL POWER LOSS
PBC TEMPERATURE
TOTAL COMPONENT AREA
MAX HEIGHT
PASSIVE
TYPICAL

FIG. 6B

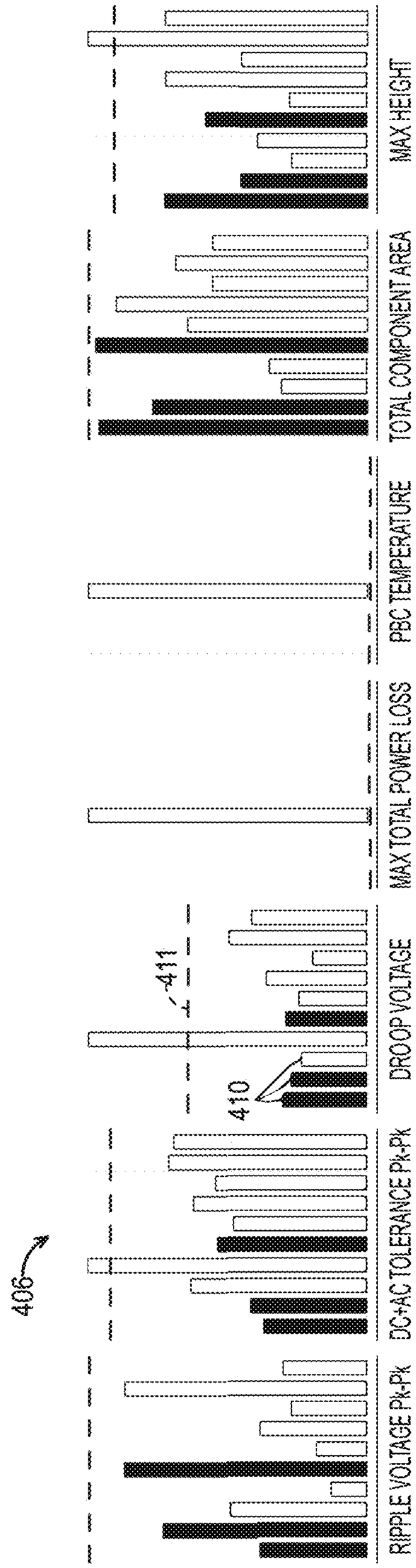

406
RIPPLE VOLTAGE Pk-Pk
DC+AC TOLERANCE Pk-Pk
410
411
DROOP VOLTAGE
408
MAX TOTAL POWER LOSS
PBC TEMPERATURE
MAX HEIGHT
TOTAL COMPONENT AREA

FIG. 7

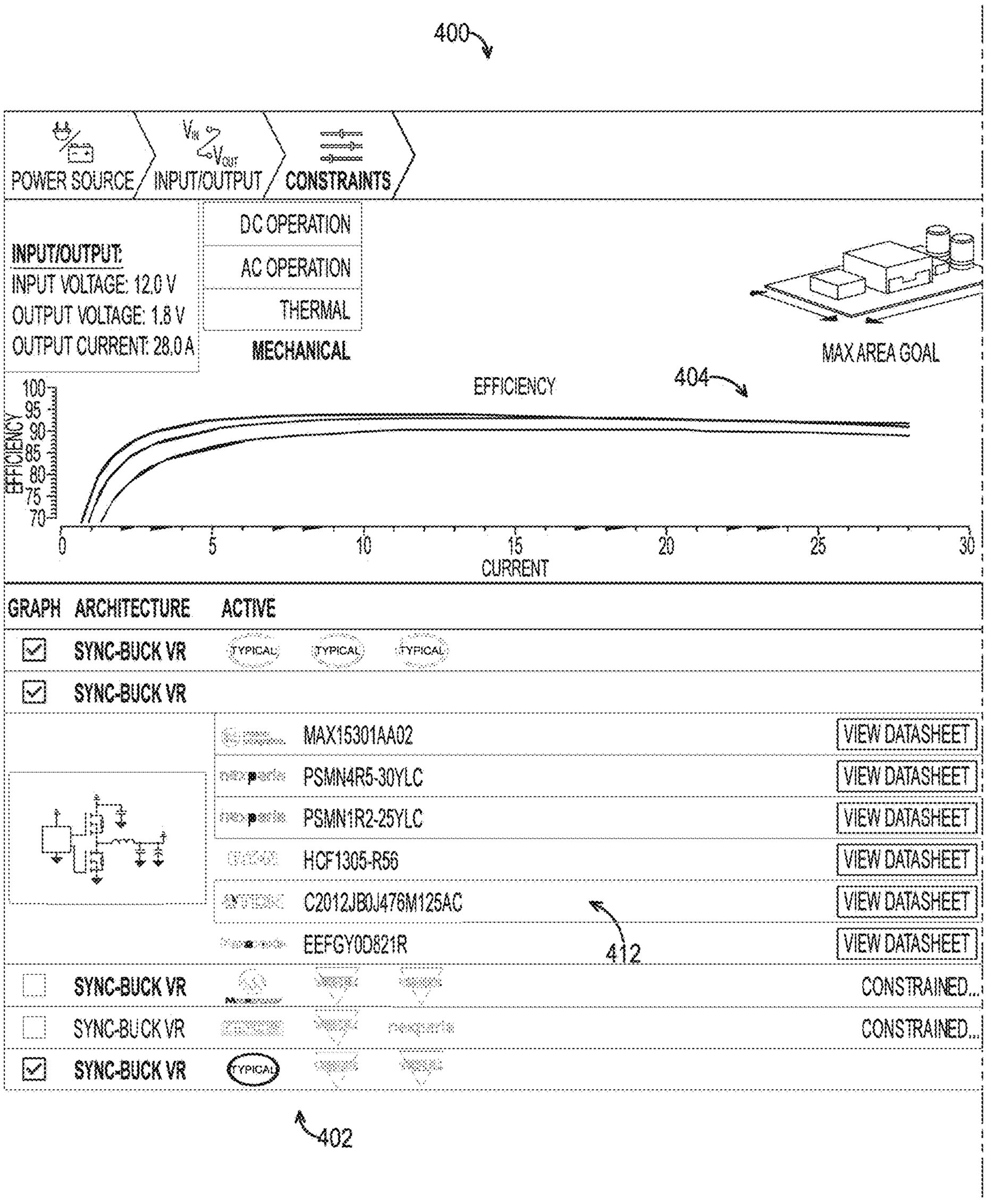

400
POWER SOURCE
INPUT/OUTPUT
CONSTRAINTS
INPUT/OUTPUT:
INPUT VOLTAGE: 12.0 V
OUTPUT VOLTAGE: 1.8 V
OUTPUT CURRENT: 28.0 A
DC OPERATION
AC OPERATION
THERMAL
MECHANICAL
MAX AREA GOAL
404
EFFICIENCY
100
95
90
85
80
75
70
0
5
10
15
20
25
30
CURRENT
GRAPH
ARCHITECTURE
ACTIVE
SYNC-BUCK VR
TYPICAL
TYPICAL
TYPICAL
SYNC-BUCK VR
MAX15301AA02
VIEW DATASHEET
PSMN4R5-30YLC
VIEW DATASHEET
PSMN1R2-25YLC
VIEW DATASHEET
HCF1305-R56
VIEW DATASHEET
C2012JB0J476M125AC
VIEW DATASHEET
412
EEFGY0D821R
VIEW DATASHEET
SYNC-BUCK VR
CONSTRAINED...
SYNC-BUCK VR
CONSTRAINED...
SYNC-BUCK VR
TYPICAL
402

FIG. 8A

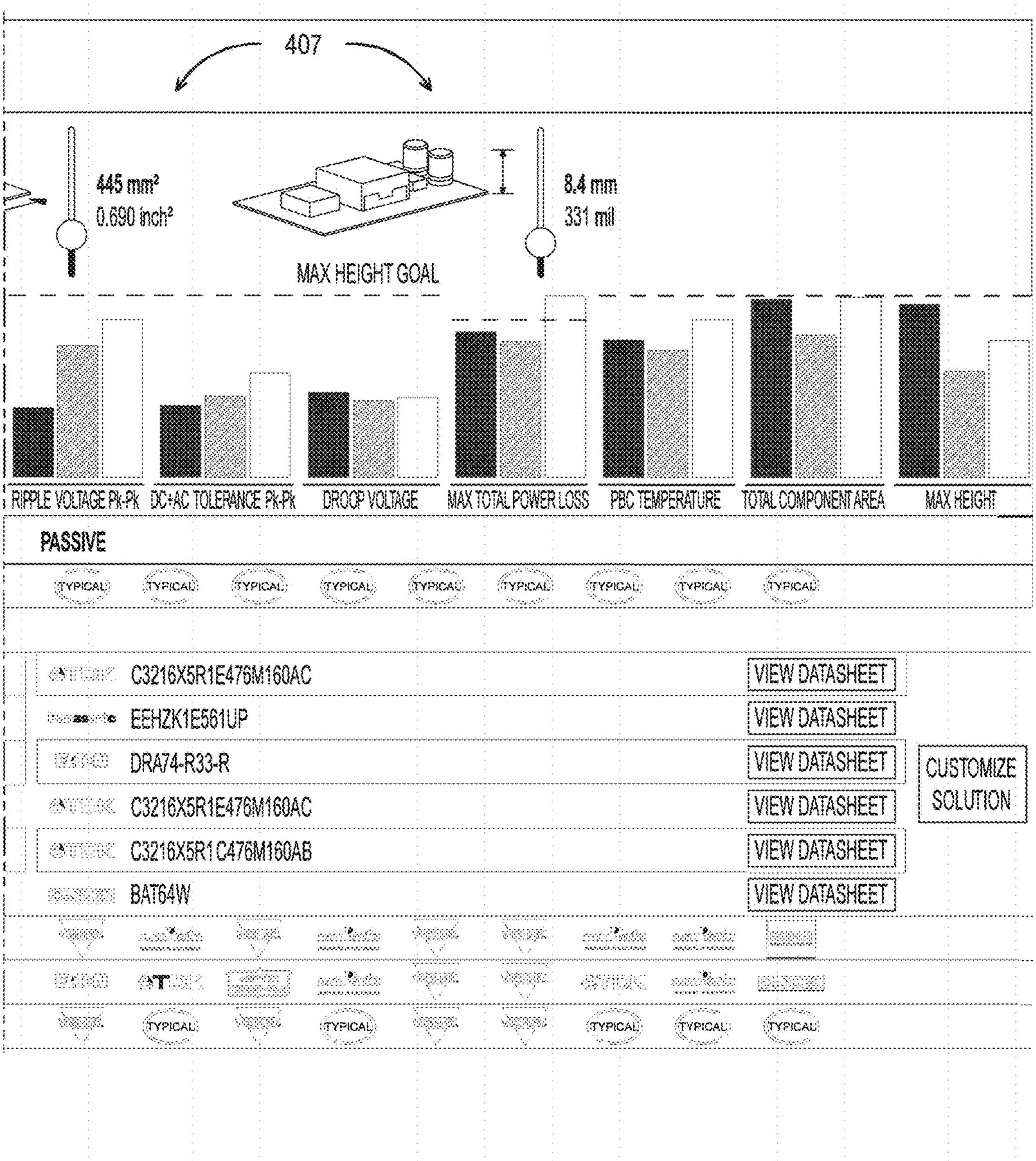

407
445 mm²
0.690 inch²
8.4 mm
331 mil
MAX HEIGHT GOAL
RIPPLE VOLTAGE Pk-Pk
DC+AC TOLERANCE Pk-Pk
DROOP VOLTAGE
MAX TOTAL POWER LOSS
PBC TEMPERATURE
TOTAL COMPONENT AREA
MAX HEIGHT
PASSIVE
TYPICAL
C3216X5R1E476M160AC
VIEW DATASHEET
EEHZK1E561UP
VIEW DATASHEET
DRA74-R33-R
VIEW DATASHEET
C3216X5R1E476M160AC
VIEW DATASHEET
C3216X5R1C476M160AB
VIEW DATASHEET
BAT64W
VIEW DATASHEET
CUSTOMIZE SOLUTION

FIG. 8B

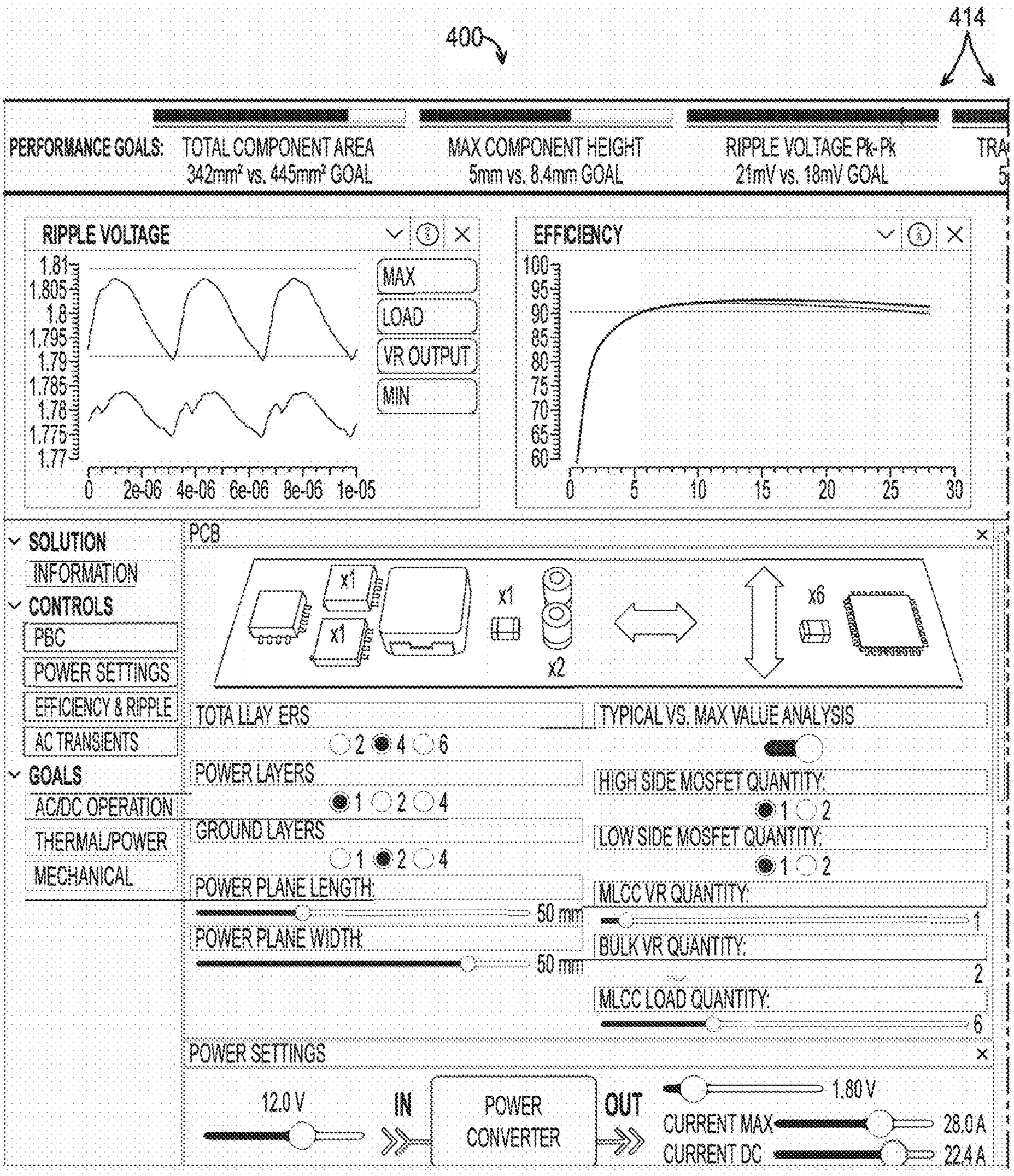

400
414
PERFORMANCE GOALS:
TOTAL COMPONENT AREA
342mm² vs. 445mm² GOAL
MAX COMPONENT HEIGHT
5mm vs. 8.4mm GOAL
RIPPLE VOLTAGE Pk-Pk
21mV vs. 18mV GOAL
TRA
5
RIPPLE VOLTAGE
1.81
1.805
1.8
1.795
1.79
1.785
1.78
1.775
1.77
0
2e-06
4e-06
6e-06
8e-06
1e-05
MAX
LOAD
VR OUTPUT
MIN
EFFICIENCY
100
95
90
85
80
75
70
65
60
0
5
10
15
20
25
30
SOLUTION
INFORMATION
CONTROLS
PDC
POWER SETTINGS
EFFICIENCY & RIPPLE
AC TRANSIENTS
GOALS
AC/DC OPERATION
THERMAL/POWER
MECHANICAL
PCB
x1
x1
x1
x2
x6
TOTA LLAY ERS
2 4 6
POWER LAYERS
1 2 4
GROUND LAYERS
1 2 4
POWER PLANE LENGTH:
50 mm
POWER PLANE WIDTH:
50 mm
TYPICAL VS. MAX VALUE ANALYSIS
HIGH SIDE MOSFET QUANTITY:
1 2
LOW SIDE MOSFET QUANTITY:
1 2
MLCC VR QUANTITY:
1
BULK VR QUANTITY:
2
MLCC LOAD QUANTITY:
6
POWER SETTINGS
12.0 V
IN
POWER
CONVERTER
OUT
1.80 V
CURRENT MAX
28.0 A
CURRENT DC
22.4 A

FIG. 9A

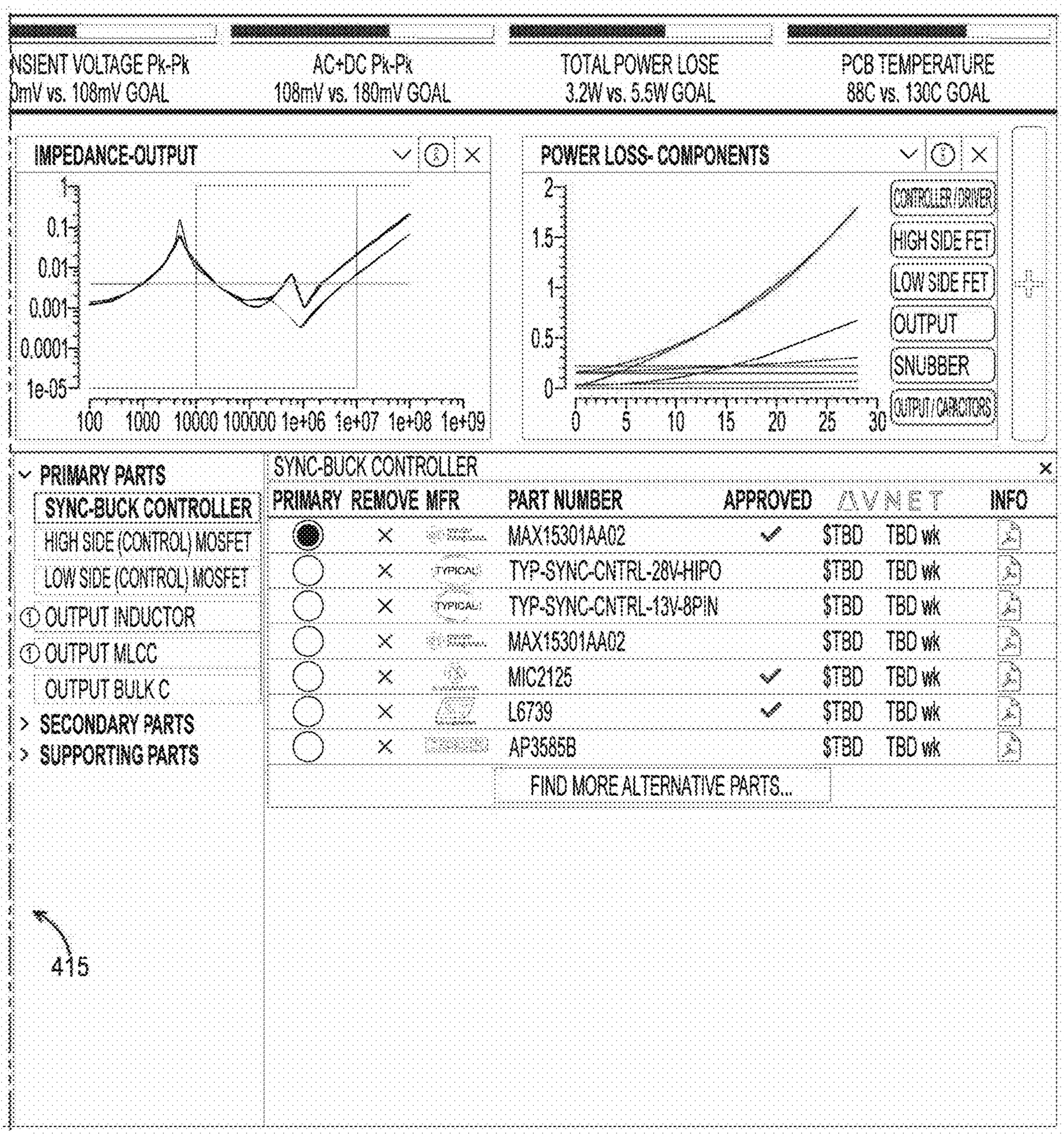

NSIENT VOLTAGE Pk-Pk
0mV vs. 108mV GOAL
AC+DC Pk-Pk
108mV vs. 180mV GOAL
TOTAL POWER LOSE
3.2W vs. 5.5W GOAL
PCB TEMPERATURE
88C vs. 130C GOAL
IMPEDANCE-OUTPUT
1
0.1
0.01
0.001
0.0001
1e-05
100 1000 10000 100000 1e+06 1e+07 1e+08 1e+09
POWER LOSS- COMPONENTS
2
1.5
1
0.5
0
0 5 10 15 20 25 30
CONTROLLER/DRIVER
HIGH SIDE FET
LOW SIDE FET
OUTPUT
SNUBBER
OUTPUT CAPACITORS
PRIMARY PARTS
SYNC-BUCK CONTROLLER
HIGH SIDE (CONTROL) MOSFET
LOW SIDE (CONTROL) MOSFET
① OUTPUT INDUCTOR
① OUTPUT MLCC
OUTPUT BULK C
> SECONDARY PARTS
> SUPPORTING PARTS
SYNC-BUCK CONTROLLER
PRIMARY REMOVE MFR PART NUMBER APPROVED AVNET INFO
MAX15301AA02 ✓ $TBD TBD wk
TYPICAL TYP-SYNC-CNTRL-28V-HIPO $TBD TBD wk
TYPICAL TYP-SYNC-CNTRL-13V-8PIN $TBD TBD wk
MAX15301AA02 $TBD TBD wk
MIC2125 ✓ $TBD TBD wk
L6739 ✓ $TBD TBD wk
AP3585B $TBD TBD wk
FIND MORE ALTERNATIVE PARTS...
415

FIG. 9B

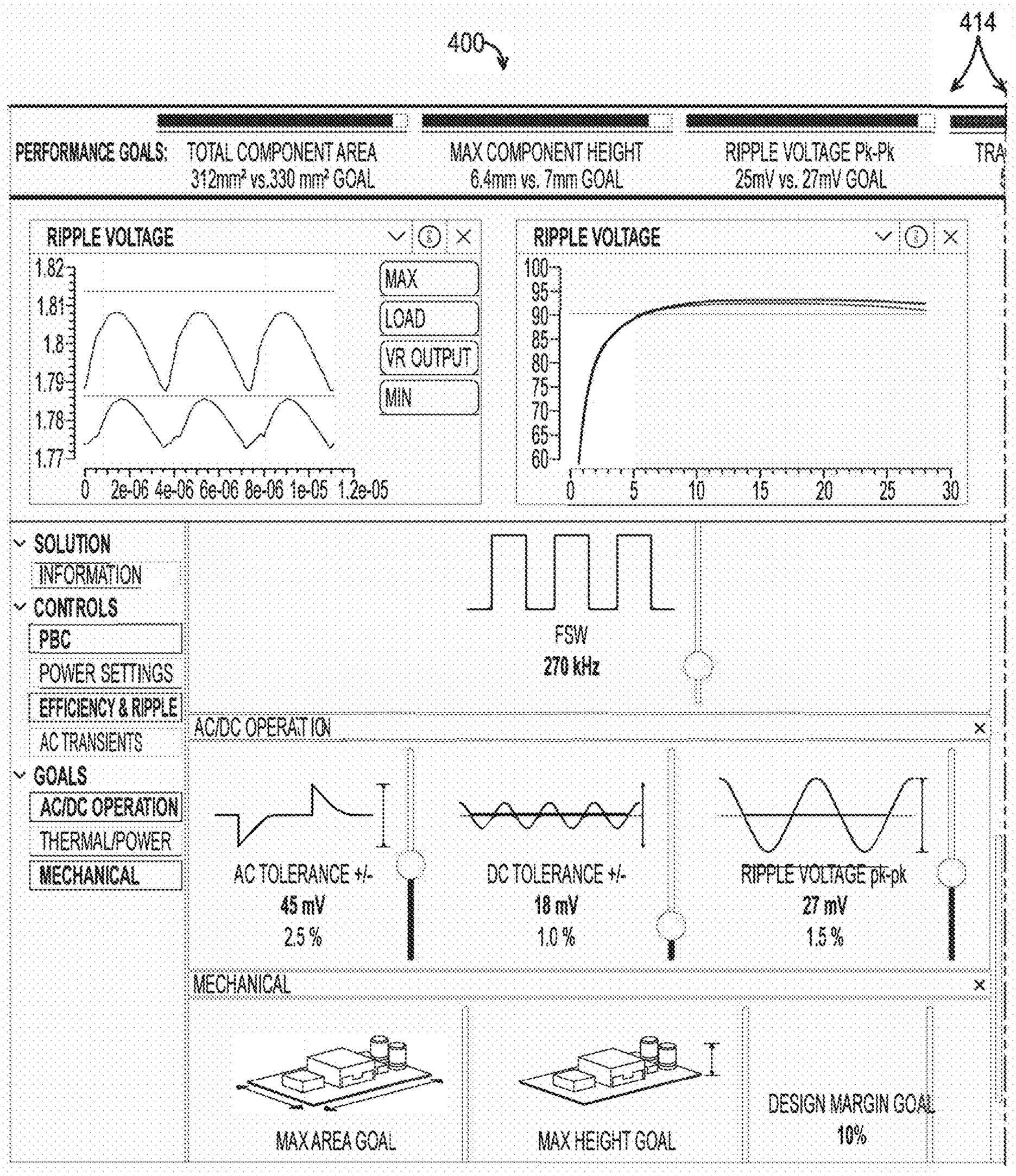

400
414
PERFORMANCE GOALS:
TOTAL COMPONENT AREA
312mm² vs.330 mm² GOAL
MAX COMPONENT HEIGHT
6.4mm vs. 7mm GOAL
RIPPLE VOLTAGE Pk-Pk
25mV vs. 27mV GOAL
TRA
RIPPLE VOLTAGE
MAX
LOAD
VR OUTPUT
MIN
1.82
1.81
1.8
1.79
1.78
1.77
0 2e-06 4e-06 6e-06 8e-06 1e-05 1.2e-05
RIPPLE VOLTAGE
100
95
90
85
80
75
70
65
60
0 5 10 15 20 25 30
SOLUTION
INFORMATION
CONTROLS
PBC
POWER SETTINGS
EFFICIENCY & RIPPLE
AC TRANSIENTS
GOALS
AC/DC OPERATION
THERMAL/POWER
MECHANICAL
FSW
270 kHz
AC/DC OPERATION
AC TOLERANCE +/-
45 mV
2.5 %
DC TOLERANCE +/-
18 mV
1.0 %
RIPPLE VOLTAGE pk-pk
27 mV
1.5 %
MECHANICAL
MAX AREA GOAL
MAX HEIGHT GOAL
DESIGN MARGIN GOAL
10%
416

FIG. 10A

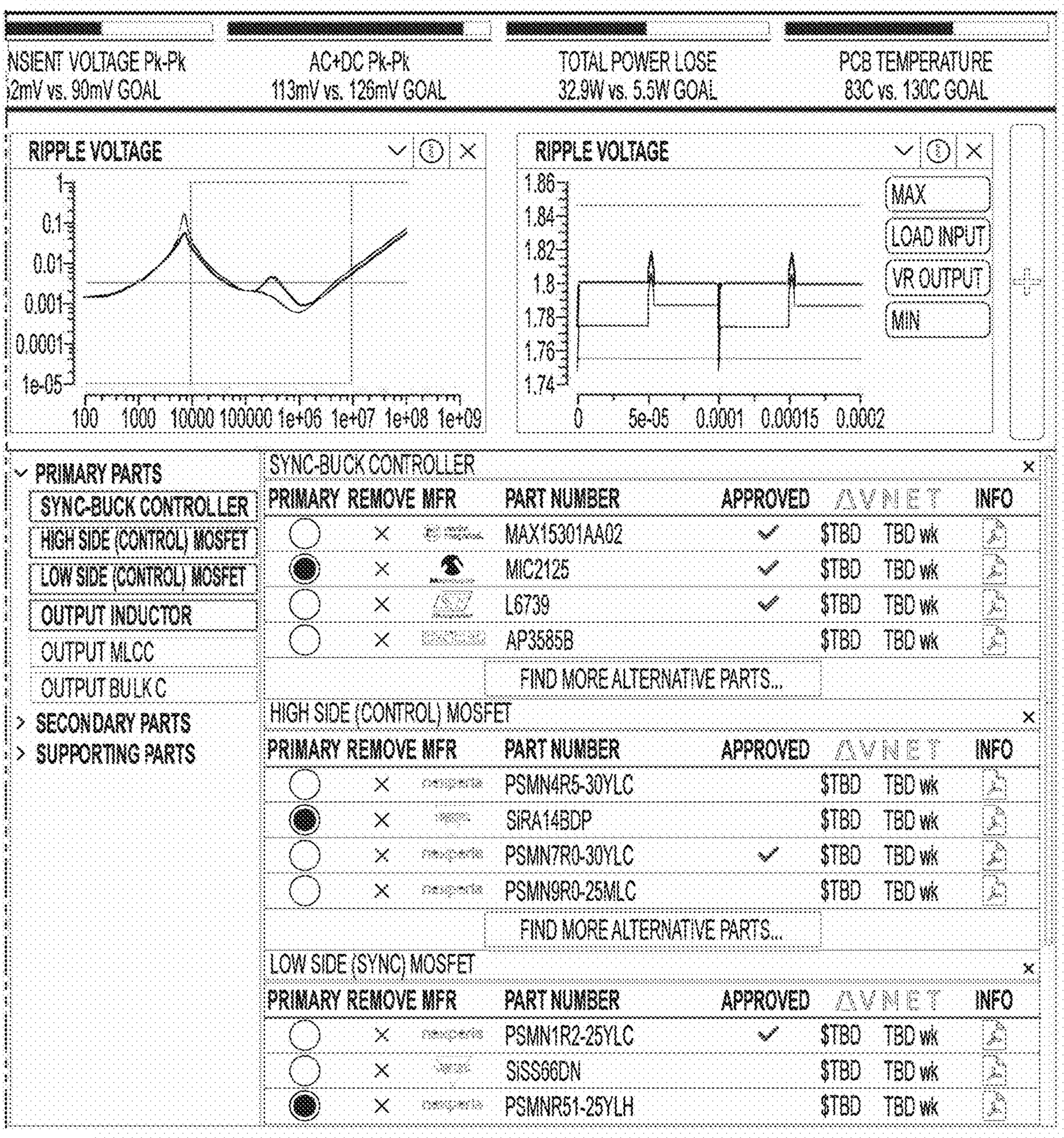

NSIENT VOLTAGE Pk-Pk
2mV vs. 90mV GOAL
AC+DC Pk-Pk
113mV vs. 126mV GOAL
TOTAL POWER LOSE
32.9W vs. 5.5W GOAL
PCB TEMPERATURE
83C vs. 130C GOAL
RIPPLE VOLTAGE
1
0.1
0.01
0.001
0.0001
1e-05
100 1000 10000 100000 1e+06 1e+07 1e+08 1e+09
RIPPLE VOLTAGE
1.86
1.84
1.82
1.8
1.78
1.76
1.74
0 5e-05 0.0001 0.00015 0.0002
MAX
LOAD INPUT
VR OUTPUT
MIN
PRIMARY PARTS
SYNC-BUCK CONTROLLER
HIGH SIDE (CONTROL) MOSFET
LOW SIDE (CONTROL) MOSFET
OUTPUT INDUCTOR
OUTPUT MLCC
OUTPUT BULK C
SECONDARY PARTS
SUPPORTING PARTS
SYNC-BUCK CONTROLLER
PRIMARY REMOVE MFR PART NUMBER APPROVED AVNET INFO
MAX15301AA02 ✓ $TBD TBD wk
MIC2125 ✓ $TBD TBD wk
L6739 ✓ $TBD TBD wk
AP3585B $TBD TBD wk
FIND MORE ALTERNATIVE PARTS...
HIGH SIDE (CONTROL) MOSFET
PRIMARY REMOVE MFR PART NUMBER APPROVED AVNET INFO
PSMN4R5-30YLC $TBD TBD wk
SiRA14BDP $TBD TBD wk
PSMN7R0-30YLC ✓ $TBD TBD wk
PSMN9R0-25MLC $TBD TBD wk
FIND MORE ALTERNATIVE PARTS...
LOW SIDE (SYNC) MOSFET
PRIMARY REMOVE MFR PART NUMBER APPROVED AVNET INFO
PSMN1R2-25YLC ✓ $TBD TBD wk
SiSS66DN $TBD TBD wk
PSMNR51-25YLH $TBD TBD wk

FIG. 10B

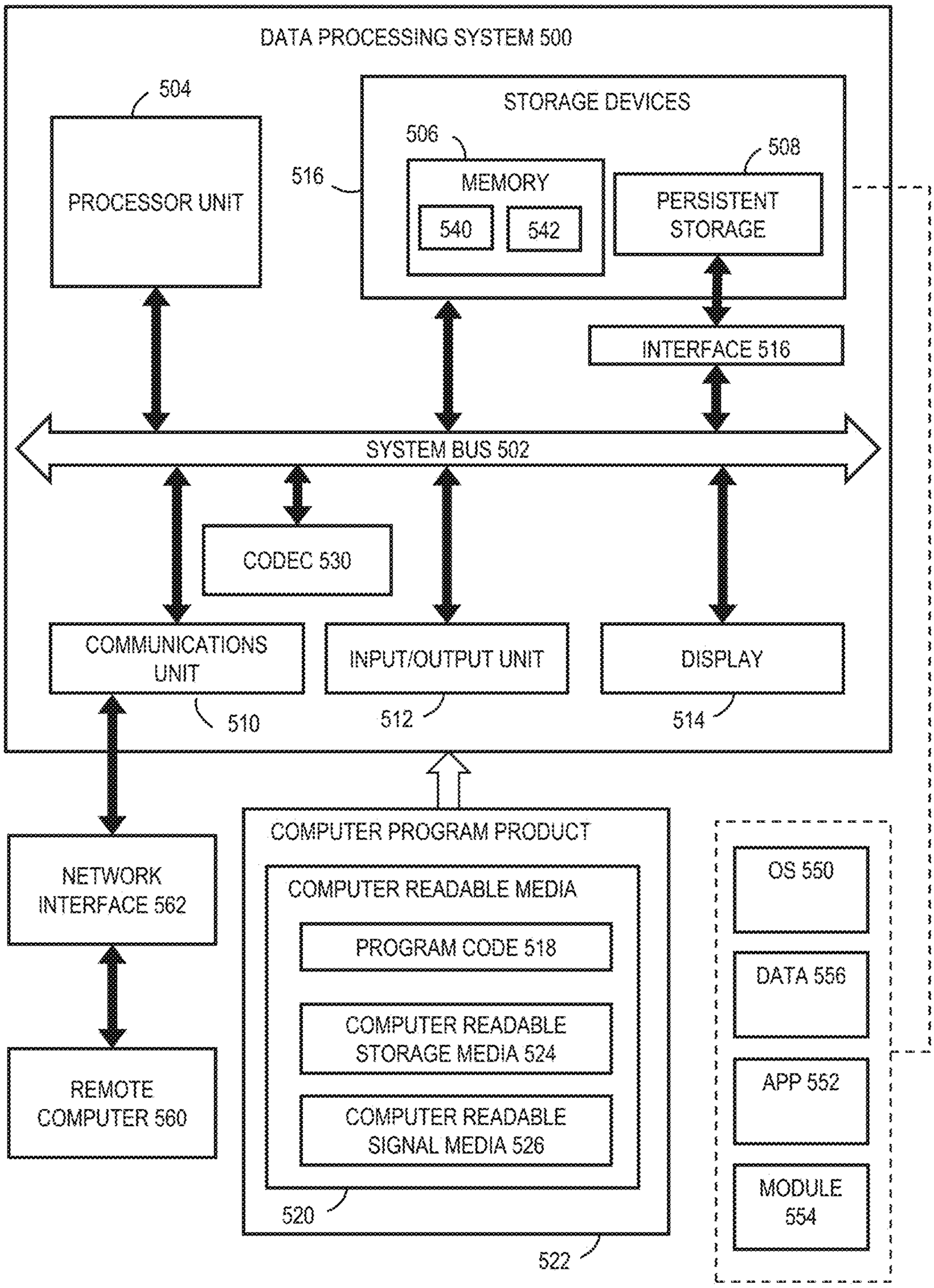

DATA PROCESSING SYSTEM 500
504
PROCESSOR UNIT
STORAGE DEVICES
506
MEMORY
540
542
516
508
PERSISTENT STORAGE
INTERFACE 516
SYSTEM BUS 502
CODEC 530
COMMUNICATIONS UNIT
510
INPUT/OUTPUT UNIT
512
DISPLAY
514
NETWORK INTERFACE 562
REMOTE COMPUTER 560
COMPUTER PROGRAM PRODUCT
COMPUTER READABLE MEDIA
PROGRAM CODE 518
COMPUTER READABLE STORAGE MEDIA 524
COMPUTER READABLE SIGNAL MEDIA 526
520
522
OS 550
DATA 556
APP 552
MODULE 554

FIG. 11

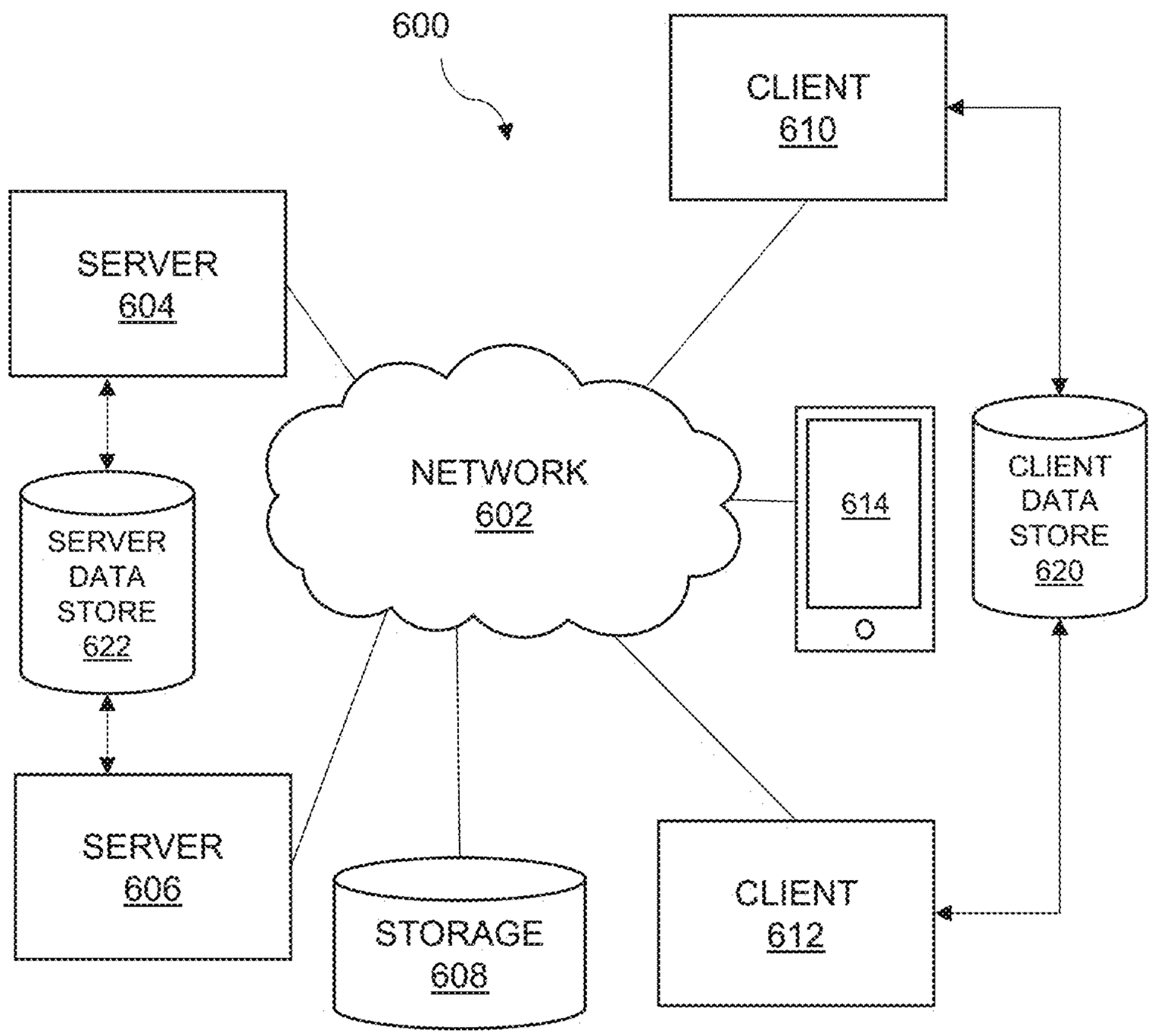

600
CLIENT
610
SERVER
604
NETWORK
602
614
CLIENT
DATA
STORE
620
SERVER
DATA
STORE
622
SERVER
606
STORAGE
608
CLIENT
612

FIG. 12

INTERACTIVE SYSTEM FOR GUIDING ELECTRONICS DESIGN AND ASSEMBLY

CROSS-REFERENCES

[0001] The following applications and materials are incorporated herein, in their entireties, for all purposes: U.S. Provisional Patent Application Ser. No. 62/901,588, filed Sep. 17, 2019; and U.S. patent application Ser. No. 17/024,567, filed Sep. 17, 2020, now U.S. Pat. No. 11,216,605.

FIELD

[0002] This disclosure relates to systems and methods for guiding electronics design and development. More specifically, the disclosed embodiments relate to a design aid for electronics and distributed framework for hosting a suite of applications relating to the design of electrical and electronic systems.

INTRODUCTION

[0003] The traditional development process for designing digital and analog electronics often begins with thorough research on component selection. The process of selecting components substantially increases the development time due to the vast selection and performance differences of all available components. As more time is spent on component research, a designer may need to sacrifice time spent on validation and integration of the final product. Additionally, as the design process continues, refining of the design through testing, validation, and integration may elicit a change in components that can be costly and time consuming.

SUMMARY

[0004] The present disclosure provides systems, apparatuses, and methods relating to guiding electronics design and development.

[0005] In some embodiments, a computer implemented method for electronics design may include: receiving, via a graphical user interface (GUI), first information including a selected type of electronic circuit assembly and one or more criteria relating to the selected type of electronic circuit assembly; for each one of a plurality of subtypes of the selected type of electronic circuit assembly: simultaneously displaying, via the GUI, a plurality of circuit assemblies satisfying the first information, wherein each of the circuit assemblies comprises a respective configuration of circuit components, and a plurality of graphical visualizations, each of the plurality of graphical visualizations displaying how each of the plurality of circuit assemblies relates to the one or more criteria; receiving, via the GUI, a user selection from the plurality of circuit assemblies to define a selected circuit assembly; and displaying, via the GUI, detailed information regarding the selected circuit assembly, including a listing of specific components included in the selected circuit assembly.

[0006] In some embodiments, a data processing system for designing electronics may include: one or more processors; a memory; and an electronics design program including a plurality of instructions stored in the memory and executable by the one or more processors to: receive, via a graphical user interface (GUI), first information including a selected type of electronic circuit assembly and one or more criteria relating to the selected type of electronic circuit; for each one of a plurality of subtypes of the selected type: simultaneously display, via the GUI, a set of circuit assemblies satisfying the first information, wherein each of the circuit assemblies comprises a respective configuration of circuit components, and a plurality of graphical visualizations, each of the plurality of graphical visualizations corresponding to how each of the circuit assemblies relates to the one or more criteria; receive, via the GUI, a user selection from the set of circuit assemblies to define a selected circuit assembly; and display, via the GUI, detailed information regarding the selected circuit assembly, including a simulation of electronic behavior of the selected circuit assembly and a listing of specific components included in the selected circuit assembly.

[0007] Features, functions, and advantages may be achieved independently in various embodiments of the present disclosure, or may be combined in yet other embodiments, further details of which can be seen with reference to the following description and drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0008] FIG. **1** is schematic view of an illustrative interactive system for guiding electronics design and assembly.

[0009] FIG. **2** is a schematic view of an illustrative electronics design aid.

[0010] FIG. **3** is a flowchart depicting steps of a method performed by the interactive system.

[0011] FIG. **4**A is a first partial view of an illustrative first user interface configured to carry out steps of the method of FIG. **3**.

[0012] FIG. **4**B is a second partial view of the illustrative first user interface.

[0013] FIG. **5**A is a first partial view of an illustrative second user interface configured to carry out steps of the method of FIG. **3**.

[0014] FIG. **5**B is a second partial view of the illustrative second user interface FIG. **6**A is a first partial view of an illustrative third user interface configured to carry out steps of the method of FIG. **3**.

[0015] FIG. **6**B is a second partial view of the illustrative third user interface.

[0016] FIG. **7** is a magnified portion of the second user interface.

[0017] FIG. **8**A is a first partial view of an illustrative fourth user interface configured to carry out steps of the method of FIG. **3**.

[0018] FIG. **8**B is a second partial view of the illustrative fourth user interface.

[0019] FIG. **9**A is a first partial view of an illustrative fifth user interface configured to carry out steps of the method of FIG. **3**.

[0020] FIG. **9**B is a second partial view of the illustrative fifth user interface.

[0021] FIG. **10**A is a first partial view of an illustrative sixth user interface configured to carry out steps of the method of FIG. **3**.

[0022] FIG. **10**B is a second partial view of the illustrative sixth user interface.

[0023] FIG. **11** is a schematic view of an illustrative data processing system suitable for use with aspects of the present disclosure.

[0024] FIG. **12** is a schematic view of an illustrative computer network suitable for use with aspects of the present disclosure.

DETAILED DESCRIPTION

[0025] Various aspects and examples of an interactive system for guiding electronics design and assembly are described below and illustrated in the associated drawings. Unless otherwise specified, an interactive system to aid in the design of electronics accordance with the present teachings, and/or its various components, may contain at least one of the structures, components, functionalities, and/or variations described, illustrated, and/or incorporated herein. Furthermore, unless specifically excluded, the process steps, structures, components, functionalities, and/or variations described, illustrated, and/or incorporated herein in connection with the present teachings may be included in other similar devices and methods, including being interchangeable between disclosed embodiments. The following description of various examples is merely illustrative in nature and is in no way intended to limit the disclosure, its application, or uses. Additionally, the advantages provided by the examples and embodiments described below are illustrative in nature and not all examples and embodiments provide the same advantages or the same degree of advantages.

[0026] This Detailed Description includes the following sections, which follow immediately below: (1) Definitions; (2) Overview; (3) Examples, Components, and Alternatives; (4) Advantages, Features, and Benefits; and (5) Conclusion. The Examples, Components, and Alternatives section is further divided into subsections, each of which is labeled accordingly.

Definitions

[0027] The following definitions apply herein, unless otherwise indicated.

[0028] "Comprising," "including," and "having" (and conjugations thereof) are used interchangeably to mean including but not necessarily limited to, and are open-ended terms not intended to exclude additional, unrecited elements or method steps.

[0029] Terms such as "first", "second", and "third" are used to distinguish or identify various members of a group, or the like, and are not intended to show serial or numerical limitation.

[0030] "AKA" means "also known as," and may be used to indicate an alternative or corresponding term for a given element or elements.

[0031] "Coupled" means connected, either permanently or releasably, whether directly or indirectly through intervening components.

[0032] "AI" means "artificial intelligence" and may be used to indicate a machine learning model, adaptive learning model, evolutionary/genetic algorithm, and/or any other artificial system configured to behave in a manner analogous to human intelligence.

[0033] "Processing logic" means any suitable device(s) or hardware configured to process data by performing one or more logical and/or arithmetic operations (e.g., executing coded instructions). For example, processing logic may include one or more processors (e.g., central processing units (CPUs) and/or graphics processing units (GPUs)), microprocessors, clusters of processing cores, FPGAs (field-programmable gate arrays), artificial intelligence (AI) accelerators, digital signal processors (DSPs), and/or any other suitable combination of logic hardware. "Assembly" means an electronics circuit or arrangement of hardware comprising passive and/or active electronics components.

[0034] When discussing electrical and electronic circuits and their components: "V" indicates volts; "A" indicates amps, "AC" indicates alternating current; "PCB" indicates printed circuit board; and "DC" indicates direct current.

[0035] "UI" means user interface, and "GUI" means graphical user interface, each of which is an example of a human-machine interface, or HMI.

[0036] In this disclosure, one or more publications, patents, and/or patent applications may be incorporated by reference. However, such material is only incorporated to the extent that no conflict exists between the incorporated material and the statements and drawings set forth herein. In the event of any such conflict, including any conflict in terminology, the present disclosure is controlling.

Overview

[0037] In general, an interactive system for guiding electronics design and development according to the present disclosure includes (1) a distributed framework for hosting a suite of applications developed to aid in the design of electronics systems and devices and (2) an electronics design aid that utilizes the distributed framework and communicates with the applications hosted on the distributed framework. The distributed framework comprises a cloud service that includes a central database and a central AI module. The distributed framework is configured to provide data from the central database. The framework is also configured to provide categorization and learning from the central AI module to the electronics design aid and hosted applications. The electronics design aid is configured to model electronics assemblies, recommend components, and adapt to (and learn from) users. Various AI modules may be incorporated, such as a context AI module, a corporate AI module, and a trust AI module, all of which are described further below.

[0038] The central database is configured to host data (e.g., in the form of datasheets) corresponding to components that may be provided by manufacturers and/or users. Datasheets and other data structures hosted on the database may be analyzed by processing logic (e.g., configured to utilize optical character recognition) to determine and/or categorize any information contained therein, such as component specific values (e.g., resistance, capacitance, inductance, etc.), operating conditions and/or constraining conditions (e.g., operating temperatures, minimum/maximum current, etc.), as well as any analytical information (e.g., clock cycles, duty cycles, mathematical functions, etc.). The information gathered by the processing logic may be stored, e.g., in the central database.

[0039] In addition to the central database, the distributed framework is configured to host a suite of third-party applications. A third party may provide a tool configured to aid in the design of electronic assemblies, and the framework is configured to seamlessly integrate the tool into its operating structure. The third-party tool may access the information contained in the database and be utilized in combination with any other applications hosted in the framework. In this manner, the third-party tool may function as a "plugin" to the framework and may be used as a part of the overall system.

[0040] In some examples, the distributed framework utilizes processing logic to combine data from a selected

plurality of components in the database and provide an estimation of performance for the combination of those components. For example, the processing logic may calculate the output of a circuit containing multiple components, connected in a given arrangement, when provided a specific input.

[0041] In some examples, the electronics design aid includes processing logic configured to receive as input a desired behavior for an electronic circuit (e.g., a specific input and a desired output) and in response to generate a collection of components and configurations that provide the desired behavior. The components and configurations provided may be categorized by several metrics, including cost, performance, availability, and/or the like. The categorization may function as a list of recommendations, a ranked list, an ordered list, an unordered list, and/or the like. For example, a designer user may provide a set of criteria, such as an input voltage and desired output voltage, along with a set of operating conditions, such as a maximum operating temperature. In this example, the electronics design aid then provides a list of one or more candidate components and configurations that provide the desired output voltage within the operating temperature.

[0042] In some examples, the electronics design aid utilizes a context AI module configured to adaptively learn how a user interacts with the interactive system. A generic, default profile may be assigned to new users that allows for simple use of the interactive system. As the user spends more time interacting with the interactive system, the context AI module will use the user's interactions as training data to categorize the user, and to learn and adapt to the user's trends and development patterns. This may include adapting the user interface to hide unused features, recommending components from the most-used manufacturers, recommending components based on development patterns, etc., based on previous user interactions.

[0043] In conjunction with the context AI module, the electronics design aid in some examples utilizes a corporate AI module that is configured to learn from a group of users working for the same entity. The corporate AI module communicates with each context AI module and aggregates the data to learn entity-wide trends, preferences, etc. The corporate AI module is a parent node to the respective context AI modules that are aggregated.

[0044] In some examples, the corporate AI modules from all entities utilizing the electronics design aid are further aggregated into a central AI module. The central AI module communicates with each of the corporate AI modules to learn global trends in the electronics market as well as manufacturer-specific trends in reliability and availability across the market.

[0045] Utilizing the data from the context AI, corporate AI, and/or central AI modules, the electronics design aid in some examples employs a trust AI module that is trained to assign one or more trust values to each manufacturer, based on historical performance and other data. The trust AI module recognizes both short-term and long-term trust values depending on several factors, including availability of components, reliability of components, customer approval, frequency of use, availability of component information, certified designs, and level of customer support.

[0046] Aspects of the interactive system, including both the electronics design aid and the distributed framework, may be embodied as a computer method, computer system, or computer program product. Accordingly, aspects of the interactive system may take the form of an entirely hardware embodiment, an entirely software embodiment (including firmware, resident software, micro-code, and the like), or an embodiment combining software and hardware aspects, all of which may generally be referred to herein as a "circuit," "module," or "system." Furthermore, aspects of the interactive system may take the form of a computer program product embodied in a computer-readable medium (or media) having computer-readable program code/instructions embodied thereon.

[0047] Any combination of computer-readable media may be utilized. Computer-readable media can be a computer-readable signal medium and/or a computer-readable storage medium. A computer-readable storage medium may include an electronic, magnetic, optical, electromagnetic, infrared, and/or semiconductor system, apparatus, or device, or any suitable combination of these. More specific examples of a computer-readable storage medium may include the following: an electrical connection having one or more wires, a portable computer diskette, a hard disk, a random access memory (RAM), a read-only memory (ROM), an erasable programmable read-only memory (EPROM or Flash memory), an optical fiber, a portable compact disc read-only memory (CD-ROM), an optical storage device, a magnetic storage device, and/or any suitable combination of these and/or the like. In the context of this disclosure, a computer-readable storage medium may include any suitable non-transitory, tangible medium that can contain or store a program for use by or in connection with an instruction execution system, apparatus, or device.

[0048] A computer-readable signal medium may include a propagated data signal with computer-readable program code embodied therein, for example, in baseband or as part of a carrier wave. Such a propagated signal may take any of a variety of forms, including, but not limited to, electromagnetic, optical, and/or any suitable combination thereof. A computer-readable signal medium may include any computer-readable medium that is not a computer-readable storage medium and that is capable of communicating, propagating, or transporting a program for use by or in connection with an instruction execution system, apparatus, or device.

[0049] Program code embodied on a computer-readable medium may be transmitted using any appropriate medium, including but not limited to wireless, wireline, optical fiber cable, RF, and/or the like, and/or any suitable combination of these.

[0050] Computer program code for carrying out operations for aspects of the interactive system may be written in one or any combination of programming languages, including an object-oriented programming language (such as Java, C++), conventional procedural programming languages (such as C), and functional programming languages (such as Haskell). Mobile apps may be developed using any suitable language, including those previously mentioned, as well as Objective-C, Swift, C#, HTML5, and the like. The program code may execute entirely on a user's computer, partly on the user's computer, as a stand-alone software package, partly on the user's computer and partly on a remote computer, or entirely on the remote computer or server. In the latter scenario, the remote computer may be connected to the user's computer through any type of network, including a local area network (LAN) or a wide area network

(WAN), and/or the connection may be made to an external computer (for example, through the Internet using an Internet Service Provider).

[0051] Aspects of the interactive system may be described below with reference to flowchart illustrations and/or block diagrams of methods, apparatuses, systems, and/or computer program products. Each block and/or combination of blocks in a flowchart and/or block diagram may be implemented by computer program instructions. The computer program instructions may be programmed into or otherwise provided to processing logic (e.g., a processor of a general purpose computer, special purpose computer, field programmable gate array (FPGA), or other programmable data processing apparatus) to produce a machine, such that the (e.g., machine-readable) instructions, which execute via the processing logic, create means for implementing the functions/acts specified in the flowchart and/or block diagram block(s).

[0052] Additionally or alternatively, these computer program instructions may be stored in a computer-readable medium that can direct processing logic and/or any other suitable device to function in a particular manner, such that the instructions stored in the computer-readable medium produce an article of manufacture including instructions which implement the function/act specified in the flowchart and/or block diagram block(s).

[0053] The computer program instructions can also be loaded onto processing logic and/or any other suitable device to cause a series of operational steps to be performed on the device to produce a computer-implemented process such that the executed instructions provide processes for implementing the functions/acts specified in the flowchart and/or block diagram block(s).

[0054] Any flowchart and/or block diagram in the drawings is intended to illustrate the architecture, functionality, and/or operation of possible implementations of systems, methods, and computer program products according to aspects of the interactive system. In this regard, each block may represent a module, segment, or portion of code, which comprises one or more executable instructions for implementing the specified logical function(s). In some implementations, the functions noted in the block may occur out of the order noted in the drawings. For example, two blocks shown in succession may, in fact, be executed substantially concurrently, or the blocks may sometimes be executed in the reverse order, depending upon the functionality involved. Each block and/or combination of blocks may be implemented by special purpose hardware-based systems (or combinations of special purpose hardware and computer instructions) that perform the specified functions or acts.

Examples, Components, and Alternatives

[0055] The following sections describe selected aspects of an exemplary interactive system for guiding electronics design and assembly as well as related systems and/or methods. The examples in these sections are intended for illustration and should not be interpreted as limiting the scope of the present disclosure. Each section may include one or more distinct embodiments or examples, and/or contextual or related information, function, and/or structure.

A. Illustrative Interactive System

[0056] As shown in FIG. **1**, an interactive system **100** according to the present teachings includes a distributed framework **102** configured to receive external software applications **104** and/or an electronics design aid **106**, each configured to utilize components of distributed framework **102**. External software applications **104** may be developed specifically for use with distributed framework **102** and/or may be developed by a third-party entity, e.g., provided as an external plugin for use with distributed framework **102**. Distributed framework **102** may utilize external applications **104**, individually or in combination with each other. In some examples, external applications **104** are in communication with each other only via distributed framework **102**. For example, electronics manufacturers may develop their own third-party design tools for use with distributed framework **102**, e.g., to provide aid in the use of their components. In that example, distributed framework **102** is configured to enable the third-party design tools to work in ensemble with other applications **104** in the framework.

[0057] Distributed framework **102** comprises a cloud system **108** having a central database **110**. Central database **110** is partitioned into a plurality of central data channels **112**. Each member of the plurality of central data channels **112** is configured to contain data (e.g., operating conditions, tolerances, component specific data, etc.) on components that has been input, downloaded, uploaded, and/or saved based on data from manufacturers, users, datasheets, and/or other data sources. In some examples, the data in central database **110** is provided in part by a community of users in an open-source capacity, such that each user can provide data and check the validity of data provided by other users. In some examples, the data in central database **110** is provided by a subset of users having database-editing rights. In some examples, the data in central database **110** is provided only by the manufactures and/or distributors of the respective components. In some examples, the data in central database **110** is provided by a mixture of manufacturers, distributors, and users. In some examples, at least some of the data is read in digitally, e.g., from datasheets, utilizing optical character recognition (OCR).

[0058] Central data channels **112** are partitioned in such a way that the information on each data channel **112** is related (e.g., by component type, component function, application, manufacturer, etc.). Partitioning central database **110** into central data channels **112** facilitates faster data transfer and less strain on a distribution network. For example, a user working on an application requiring data solely from a single data channel **112**, can forego transferring data from other data channels. In one example, central data channels **112** may be partitioned such that the most commonly used components for a selected design application (e.g., power engineering) are stored together in one data channel **112**.

[0059] Cloud system **108** includes a central AI module **114**. Central AI module **114** is configured to learn and/or categorize long-term and short-term trends in the electronics industry on a global and/or regional scale by training on an aggregation of data hosted on distributed framework **102**, such as data associated with electronics design aid **106** and external applications **104** from a plurality of unique entities (e.g., corporations, companies, engineering groups).

[0060] In some examples, central AI module **114** is configured to learn trends regarding the global prevalence of purchasing from specific manufacturers. In some examples, central AI module **114** is configured to train on decisions made by users interacting with electronics design aid **106**, such as component preferences, orders of operations, manu-

facturer preferences, etc. In some examples, central AI module **114** is configured to identify changes in the use of certain components on a global scale. In this manner, central AI module **114** is configured to evaluate the successes and failures of certain products, both technically and commercially.

[0061] Cloud system **108** is in network communication with a plurality of data isolation nodes **116**. Data isolation nodes **116** may be representative of a specific company, engineering group, or corporate entity. The network communication between distributed framework **102** and data isolation nodes **116** is passed through a security filter **118** that ensures a secure isolation of each node **116**. Security filter **118** may utilize encryption algorithms such as symmetric-key algorithms (e.g., Advanced Encryption Standard (AES)), asymmetric-key algorithms (e.g., Rivest-Shamir-Adelman (RSA)), and/or other encryption algorithms. Security filter **118** allows for cross-company analysis of the industry by central AI module **114** without compromising the security of any individual company. This facilitates a global aggregate of industry knowledge that can be used in analyzing manufacturer reliability as well as changes in development across the entire electronics design industry.

[0062] Each data isolation node **116** includes a distributed corporate AI module **120** configured to be in communication with a plurality of individual instances of electronics design aid **106**. Each instance of electronics design aid **106** is configured to be utilized by individual members of a single entity, however defined (e.g., a company, engineering group, corporate entity, etc.).

[0063] The distribution of corporate AI module **120** across each instance of electronics design aid **106** forms a distributed AI network configured to learn trends of all members of the entity. Distributed corporate AI module **120** is configured to be a collective monitoring system that analyzes choices (e.g., preferences, component use, manufacturer preferences) of each member in the entity. Distributed corporate AI module **120** aggregates data from each instance of electronics design aid **106** and is trained on the data to establish collective information on the entire entity. Corporate AI module **120** learns and determines which components should be recommended for certain applications, based on the overall usage of those components by the entity. The collective information gathered by a plurality of corporate AI modules **120** (each member of the plurality being from a different entity), is analyzed by central AI module **114** to determine the global trends in the industry.

[0064] Each instance of electronics design aid **106** utilized by an individual user (e.g., engineer, systems designer, technician) of a specific entity may be in network communication within a data isolation node **116** with each other entity-specific instance of electronics design aid **106**. Each instance of electronics design aid **106** can access central database **110** and duplicate specific central data channels **112** into a local database **122** having local data channels **124**. Local database **122** may be stored in local memory on an individual user's computer to decrease the strain on the network. Local data channels **124** may contain only the components that are used by the user. For example, if the user is a power engineer, local data channels **124** stored in the user's local database **122** may contain only the components that are most useful for power applications.

[0065] Each instance of electronics design aid **106** has a user-specific context AI module **126**. Context AI module **126** is configured to learn the usage trends of an individual user. Context AI module **126** may update the personal experience the user has when interacting with electronics design aid **106**. For example, context AI module **126** may learn the most common components selected by the user and communicate to electronics design aid **106** to display them first. Additionally, or alternatively, context AI module **126** may categorize the user by experience level (e.g., novice, expert, etc.) and adaptively change aspects of electronics design aid **106** accordingly. Each context AI module **126** is in network communication with corporate AI module **120** to provide the data for aggregation, as described above.

[0066] Interactive system **100** includes a trust AI module **127** in communication with cloud system **108** and the plurality of data isolation nodes **116**. Trust AI module **127** is configured to learn in conjunction with each of the AI modules, context AI module **126**, corporate AI module **120**, and central AI module **114**, to generate a trust value for each manufacturer dependent on a collection of trust factors.

[0067] The trust factors utilized by trust AI module **127** may include availability, such as past and present inventory presence, component manufacturing trends (e.g., whether overall production is increasing or decreasing), inventory levels of distribution channels, trends in distribution, and others. The trust factors may also include reliability, such as component specific quarantines and rejections, quantity of component errors, severity of component errors, recency of component errors, and others. The trust factors may also include customer approval ratings, such as relative acceptance of component in final design, usage statistics, customer ratings, and others. The trust factors may also include certified designs and common designs, including the rate of use/adoption of the certified and common designs. The trust factors may also include information availability for each component, such as depth of detail in datasheets, amount of testing information, depth of testing information, and quality of information for a component. The trust factors may also include level of support services, such as ease of contact, type of support contact (e.g., email, phone, office, support center), quality of support, timeliness of support, and others. The trust factors may also include any other custom and/or multi-source feedback on a manufacturer including 3^{rd} party rankings, standard acceptance, unique products, environmental footprints, etc.

[0068] Turning now to FIG. **2**, electronics design aid **106** includes a solution system **128** configured to generate one or more relevant electronic assemblies and associated analyses depending on a provided set of requirements from the user. Solution system **128** comprises the following elements: a solution advisor **130**, a solution selector **132**, a solution design optimizer **134**, and a solution validator **136**. Each of these elements is discussed further below.

[0069] Solution system **128** is configured to provide detailed analysis and design choices for the development of electronic circuits and assemblies when given an input from a user. Each element in solution system **128** may contribute to an overall reduction in development costs and an accelerated development cycle. More specifically, solution system **128** is generally configured to facilitate the following steps (see FIG. **3** and see also the associated method described in Section B):

[0070] 1. Primary operating criteria are established by a user. For example, if developing a DC-DC power converter,

primary operating criteria may include input voltage, output voltage, output current, and grade (e.g., tolerance, reliability, etc.).

[0071] 2. Solution system **128**, with or without feedback from the various levels of AI module described above, outputs a list of potential components and respective manufacturers/suppliers.

[0072] 3. Solution system **128** provides a list of analytical data regarding each component and allows for further selection of auxiliary operating criteria (e.g., operating temperature; electrical tolerances; size, i.e., height and/or area; etc.).

[0073] 4. As the user chooses a combination of components as suggested by solution system **128**, solution system **128** provides real-time analysis of electrical properties of the specific combination of components, as determined by relevant mathematical models.

[0074] 5. A final (or candidate) combination of components selected by the user is analyzed by solution system **128** to determine overall functionality of the combination and finalize the design.

[0075] Solution system **128** includes a solution advisor **130**, configured to output electronics architecture options (e.g., electronic circuit schematics). In general, solution system **128** is configured to receive as input one or more "critical needs" as defined by the user. The critical needs may include the basic function of the electronics assembly, the operating conditions, and/or design capacity. For example, if the user is designing a DC-DC converter, the critical needs may include producing a 5V output. The critical needs of the user are application specific.

[0076] The options for output of solution advisor **130** include circuit schematics, computer architectures, component suggestions, etc. In some examples, solution advisor **130** outputs a risk assessment for each suggested output. The risk assessment may be accomplished through statistical methods, machine learning, and/or other analytical methods. In some examples, solution advisor **130** includes an option to adaptively expand the option set through settings feedback. For example, if the user selectively introduces limitations to the required design, solution advisor **130** may adaptively change suggested outputs in real-time.

[0077] Solution system **128** includes a solution selector **132**. Solution selector **132** takes the user's prioritized requirements as input. The prioritized requirements include auxiliary characteristics the user wants to include in the final design. For example, prioritized requirements may include maximum operating temperature, input/output tolerances, size of assembly (height and area), etc. The prioritized requirements may be given by a user or may be generated by an auto selector option produced by one of the AI modules described above. For example, corporate AI module **120** may learn that other power engineers at a company tend to require a maximum operating temperature of 100° C. and generate that as a prioritized requirement with the auto selector option. Solution selector **132** is configured to utilize the user's prioritized requirements to refine the output from solution advisor **130** to include only the options that meet the prioritized requirements. In some examples, the refined output may include an indication of a match level (e.g., how close of a match the component is to the requirements) and related industry preference (e.g., as determined by the trust AI module **127** module).

[0078] Solution system **128** includes a solution design optimizer **134**. Solution design optimizer is configured to provide the user with a detailed analysis of the components selected by solution selector **132**. The detailed analysis may include analyzing operating conditions, component combinations, potential tradeoffs, etc. The detailed analysis may comprise tables, graphs, charts, and/or other data visualizations. Solution design optimizer **134** is configured to present design optimizations, for example influenced or provided by the context AI module **126**, corporate AI module **120**, and/or central AI module **114**. The AI modules learn from industry trends to identify potentially optimal designs and component selections. As a user gains experience using solution system **128** the level of optimization suggestions may change as the context AI module **126** learns how the user interacts with the system. For example, if the user is new to the system, solution design optimizer **134** may suggest optimizations based on the designs of other, more senior, designers (as learned by the context and corporate AI modules). Furthermore, if the user is a senior developer, solution design optimizer **134** may only suggest optimizations based on the industry trends as learned by central AI module **114**.

[0079] In some examples, solution design optimizer **134** provides the user with an auto-generated design based on the selections of solution selector **132**. The auto-generated designs may be generated, for example, through the use of predictive calculations, part favorability, company standards, machine learning, etc. The auto-generated designs may utilize behavioral patterns and industry knowledge from the context AI module **126**, corporate AI module **120**, and/or central AI module **114** modules to determine an order of parameter optimization.

[0080] In some examples, solution design optimizer **134** includes a collaboration mode that enables multiple users to collaborate on optimizing a design. The collaboration mode may provide any participating user the ability to suggest components and/or designs that may be collectively analyzed by solution design optimizer **134** to provide a general optimization approach.

[0081] Solution system **128** includes a solution validator **136**. Solution validator **136** is configured to analyze the full design of an electronics assembly to ensure the validity and functionality of the design. In some examples, solution validator **136** includes a review and ratification process that finalizes the electronics assembly. In some examples, solution validator outputs a final circuit schematic to an external tool (e.g., CAD) to facilitate a more seamless design flow into other electronics design tools.

B. Illustrative Method

[0082] This section describes steps of an illustrative method **300** performed by interactive system **100** for guiding electronics design and assembly. Aspects of distributed framework **102** and electronics design aid **106** described in the previous section may be utilized in the method steps described below. Where appropriate, reference may be made to components and systems that may be used in carrying out each step. These references are for illustration, and are not intended to limit the possible ways of carrying out any particular step of the method.

[0083] As described above, interactive system **100** has multiple AI modules that work in concert to guide electronics design and assembly, including electronics design aid **106** having a context AI module **126**, trust AI module **127**, and a corporate AI module **120** and distributed framework **102** having a central AI module **114**.

[0084] Electronics design aid **106** of the present embodiment includes solution system **128** configured to receive one or more operating conditions from a user for the development of an electronics assembly/design and characteristics thereof and produce one or more candidate solutions. For example, if the user is developing a DC-DC converter, the operating conditions may include the desired input voltage and desired output voltage. The list of operating condition inputs provided by the user may comprise prioritized requirements and critical needs. In some examples, the input of the operating conditions comprises a guided, step-by-step process enabled by a user interface (UI) of electronics design aid **106**.

[0085] In some examples, the user is able to choose an assembly from a list of general categories of electronics assemblies (e.g., power systems, signal filters, amplifiers, etc.). The electronics assemblies included in the list of general categories may be adaptive to the design trends of the global industry as learned by central AI module **114**. For example, if there is an increased trend of use of a new type of electronic assembly, the list may adapt to include it in the list of general categories.

[0086] In some examples, the user is then prompted to choose from a list of sub-types for the chosen general category of electronics assemblies. For example, if a user chooses "power systems" from the list of general categories, electronics design aid **106** may supply a list of power systems such as DC-DC linear regulator, DC-DC buck regulator, flyback converter, etc. For each sub-type that can be chosen, electronics design aid **106** may provide a list of example architectures (i.e. one or more basic circuit schematics) that form the basic sub-type assembly.

[0087] After a sub-type is chosen, the user may provide one or more operating criteria referred to as the "critical needs" for the desired electronics assembly. The critical needs include characteristics of the desired electronics assembly that affect the fundamental function of the assembly. The critical needs vary depending on the sub-type that is chosen and further depend on the application the electronics assembly is configured to perform. For example, if the user chooses "DC-DC linear regulator" as a sub-type, electronics design aid **106** may supply critical needs entry fields for input voltage, output voltage, max current output, etc. The type of critical needs entry fields available to the user may change depending on the sub-type chosen (i.e., only the relevant entry fields for a particular sub-type may be shown to the user).

[0088] The critical needs are utilized by electronics design aid **106** to generate a list of components that provide the sub-type function within the constraints of the critical needs. The critical needs are also utilized by electronics design aid **106** to limit the list of example architectures to those that are capable of producing sub-type function that conforms to the critical needs of the user.

[0089] After the critical needs are input, the user may provide a set of refining criteria referred to as the "prioritized requirements" for the desired electronics assembly. The prioritized requirements include characteristics of the desired electronics assembly that do not change the fundamental function but rather enable more specific customization. Generally speaking, the prioritized requirements are the user's application-specific characteristics such as tolerances, efficiencies, fault protections, etc. For example, if the user chooses "DC-DC linear regulator" as a sub-type, electronics design aid **106** may supply prioritized requirements entry fields for DC tolerance, efficiency, circuit footprint (i.e. maximum size dimension(s)), etc. The type of prioritized requirements entry fields available to the user may change depending on the sub-type chosen (i.e., only the relevant entry fields for a particular sub-type may be shown to the user).

[0090] The prioritized requirements are utilized by electronics design aid **106** to curtail the list of solutions generated within the constraints of the critical needs to those that further conform to the prioritized requirements. The prioritized requirements are also utilized by electronics design aid **106** to further limit the list of example architectures to those that conform to the prioritized requirements.

[0091] After the list of operating conditions (i.e., critical needs and prioritized requirements) is received by electronics design aid **106**, solution system **128**, e.g., in conjunction with the AI modules, outputs a list of components and configurations (AKA solutions). The output solutions are those deemed by electronics design aid **106** to conform (or attempting to conform) to the selected operating conditions (i.e., critical needs and prioritized requirements) of the user.

[0092] The user may then choose to further customize the electronics assembly according to the specific application. The electronics design assembly may enable the user to adaptively change any component and/or arrangement of components, and to graphically view the resulting behavior of the assembly.

[0093] Turning to method **300** as depicted in FIG. **3**, at step **302**, critical needs are received by electronics design aid **106**. The critical needs may be input by a user on a device such as a computer, laptop, smartphone, tablet, etc. As described above, the critical needs include the general type of electronics assembly desired (e.g., power converter, oscillator, etc.) and the basic operating function of the desired electronics assembly. For example, the critical needs may comprise a DC-DC converter configured to convert a 12V signal to a 1.8V output. In the example depicted in FIGS. **4**A and **4**B, the critical needs include: a power converter designed to receive a 12V input and convert it to a 1.8V output capable of handling up to 28A.

[0094] At step **304** of method **300**, electronics design aid **106** generates and displays a list of possible components and configurations (i.e., electrical assemblies) in accordance with the selected critical needs, and calculates and displays associated analytical data for the components and configurations. The analytical data may include graphs, charts, and/or lists of operating conditions, manufacturing tolerances, efficiency, and other relevant data. The analytical data for the individual components may be retrieved from central database **110** or local database **122**. The analytical data for the configurations may be generated in real-time from the component data and relevant mathematical models.

[0095] In the example UI **400** depicted in FIGS. **4**A and **4**B, electronics design aid **106** has generated a list of possible architectures (AKA solutions) **402** capable of producing the critical needs input by the user, namely five sync buck voltage regulators and one multi-phase voltage regulator. Additionally, electronics design aid **106** has displayed a graph **404** depicting the efficiency of each solution. As shown in the example, the critical needs are input in step **304** with sliders **405**—accordingly, list of possible solutions **402** and the accompanying graph(s) are automatically updated when a user changes a slider value.

[0096] At optional step **306** of method **300**, one or more of the AI modules described above refine the list of possible components and configurations in accordance with any learned characteristics, such as those described above.

[0097] At step **308** of method **300**, prioritized requirements are received by the electronics design aid. The prioritized requirements may be input by the user with sliders **407**, as shown in FIGS. **5**A and **5**B. The prioritized requirements include auxiliary characteristics the user wants to include in the final design. For example, prioritized requirements may include input/output tolerances, size of assembly (height and/or area), etc. In the example depicted in FIGS. **5**A and **5**B and FIG. **6**A and **6**B, the prioritized requirements include DC tolerance, peak to peak ripple voltage, maximum area goal, and maximum height goal.

[0098] At step **310** of method **300**, electronics design aid **106** refines the list of solutions **402** based on the prioritized requirements provided by the user and accordingly calculates and updates the displayed analytical data including efficiency graph **404** and a visualization in the form of a bar chart section **406**, each of the bar charts corresponding to a respective one of the prioritized requirements, and each bar of the bar charts representing a corresponding value associated with each prioritized requirement for a respective one of the solutions from list of solutions **402**.

[0099] Turning to bar chart section **406** indicated at **7** in FIG. **5**B and shown magnified in FIG. **7**, the electronics design aid is configured to show each solution's corresponding values for each of the prioritized requirements in a comparative bar chart format, wherein each bar chart **408** corresponds to a single prioritized requirement and each bar **410** corresponds to a respective solution. The user-specified prioritized requirements received in step **308** are shown respectively as a dashed threshold line **411** above each bar chart **408**. This configuration enables the user to quickly and visually reference which solutions conform to each of the prioritized requirements and which solutions fall outside of each of the prioritized requirements.

[0100] This UI configuration enables the user to make informed decisions about which solution to choose and when a certain requirement may be relaxed or changed to allow for more advantageous characteristics in other areas. For example, a solution may be just above the threshold for max height but otherwise outperform other solutions in specific (potentially more important) areas, such as droop voltage. The user may choose to adapt their selected requirements with this in mind, for example in this case by relaxing the required maximum height of the housing, thereby including more acceptable options that otherwise improve overall performance.

[0101] At step **312**, the user selects a solution from list **402** and is presented with a detailed analysis **414** (see FIGS. **9**A and **9**B) of the solution and the option to further customize the solution based on desired attributes, e.g., vendor specific components or a certain PCB layout. In the UI example of FIGS. **8**A and **8**B, the user selects a solution using a drop-down parts list **412** with associated manufacturers and a schematic view of the circuit for each of the presented solutions. When the user selects their desired solution, they are presented with the detailed analysis **414** of the solution, as shown in the example of FIGS. **9**A and **9**B. The user may then further customize the specific solution, for example by replacing individual components or changing the layout of a PCB as shown generally at **415**. For example, the user may approve of the overall solution but require the use of a specific vendor and/or manufacturer for certain components. Electronics design aid **106** automatically analyzes and updates the displayed analytical data **414** dynamically (e.g., in real time or near real time) in response to user customization.

[0102] At step **314** of method **300**, electronics design aid **106** verifies and finalizes the selection. This step may include the option for the user to access stored data for each component as well as further calculate the behavior of the combination of components according to the accessed data. Additionally, the user may be able to view the respective manufacturer(s) of each component and their associated trust score as described in the previous section. In the example of FIGS. **10**A and **10**B, the user can make final adjustments to operating conditions, e.g., using slider elements **416** of UI **400**, and electronics design aid **106** is configured to automatically flag an incompatibility with the chosen solution. Additionally, electronics design aid may identify if a chosen component has been designated as problematic by one or more of the AI modules described above (or by another user). In the finalization stage of this step, electronics design aid **106** outputs the chosen solution, for example in a specific format (e.g., CAD) for use with another program.

C. Illustrative Data Processing System

[0103] As shown in FIG. **11**, this example describes a data processing system **500** (also referred to as a computer, computing system, and/or computer system) in accordance with aspects of the present disclosure. In this example, data processing system **500** is an illustrative data processing system suitable for implementing aspects of the interactive system for guiding electronics design and assembly. More specifically, in some examples, devices that are embodiments of data processing systems (e.g., smartphones, tablets, personal computers) may be configured to process aspects of the electronics design aid and distributed framework described in previous sections. In some examples, devices that are embodiments of data processing systems may be configured to run one or more instances of the electronics design aid and/or may be configured to run one or more applications hosted by the distributed framework.

[0104] In this illustrative example, data processing system **500** includes a system bus **502** (also referred to as communications framework). System bus **502** may provide communications between a processor unit **504** (also referred to as a processor or processors), a memory **506**, a persistent storage **508**, a communications unit **510**, an input/output (I/O) unit **512**, a codec **530**, and/or a display **514**. Memory **506**, persistent storage **508**, communications unit **510**, input/output (I/O) unit **512**, display **514**, and codec **530** are examples of resources that may be accessible by processor unit **504** via system bus **502**.

[0105] Processor unit **504** serves to run instructions that may be loaded into memory **506**. Processor unit **504** may comprise a number of processors, a multi-processor core, and/or a particular type of processor or processors (e.g., a central processing unit (CPU), graphics processing unit (GPU), etc.), depending on the particular implementation. Further, processor unit **504** may be implemented using a number of heterogeneous processor systems in which a main processor is present with secondary processors on a single chip. As another illustrative example, processor unit **504**

may be a symmetric multi-processor system containing multiple processors of the same type.

[0106] Memory **506** and persistent storage **508** are examples of storage devices **516**. A storage device may include any suitable hardware capable of storing information (e.g., digital information), such as data, program code in functional form, and/or other suitable information, either on a temporary basis or a permanent basis.

[0107] Storage devices **516** also may be referred to as computer-readable storage devices or computer-readable media. Memory **506** may include a volatile storage memory **540** and a non-volatile memory **542**. In some examples, a basic input/output system (BIOS), containing the basic routines to transfer information between elements within the data processing system **500**, such as during start-up, may be stored in non-volatile memory **542**. Persistent storage **508** may take various forms, depending on the particular implementation.

[0108] Persistent storage **508** may contain one or more components or devices. For example, persistent storage **508** may include one or more devices such as a magnetic disk drive (also referred to as a hard disk drive or HDD), solid state disk (SSD), floppy disk drive, tape drive, Jaz drive, Zip drive, flash memory card, memory stick, and/or the like, or any combination of these. One or more of these devices may be removable and/or portable, e.g., a removable hard drive. Persistent storage **508** may include one or more storage media separately or in combination with other storage media, including an optical disk drive such as a compact disk ROM device (CD-ROM), CD recordable drive (CD-R Drive), CD rewritable drive (CD-RW Drive), and/or a digital versatile disk ROM drive (DVD-ROM). To facilitate connection of the persistent storage devices **508** to system bus **502**, a removable or non-removable interface is typically used, such as interface **528**.

[0109] Input/output (I/O) unit **512** allows for input and output of data with other devices that may be connected to data processing system **500** (i.e., input devices and output devices). For example, input device **532** may include one or more pointing and/or information-input devices such as a keyboard, a mouse, a trackball, stylus, touch pad or touch screen, microphone, joystick, game pad, satellite dish, scanner, TV tuner card, digital camera, digital video camera, web camera, and/or the like. These and other input devices may connect to processor unit **504** through system bus **502** via interface port(s) **536**. Interface port(s) **536** may include, for example, a serial port, a parallel port, a game port, and/or a universal serial bus (USB).

[0110] Output devices **534** may use some of the same types of ports, and in some cases the same actual ports, as input device(s) **532**. For example, a USB port may be used to provide input to data processing system **500** and to output information from data processing system **500** to an output device **534**. Output adapter **538** is provided to illustrate that there are some output devices **534** (e.g., monitors, speakers, and printers, among others) which require special adapters. Output adapters **538** may include, e.g., video and sounds cards that provide a means of connection between the output device **534** and system bus **502**. Other devices and/or systems of devices may provide both input and output capabilities, such as remote computer(s) **560**. Display **514** may include any suitable human-machine interface or other mechanism configured to display information to a user, e.g., a CRT, LED, or LCD monitor or screen, etc.

[0111] Communications unit **510** refers to any suitable hardware and/or software employed to provide for communications with other data processing systems or devices. While communication unit **510** is shown inside data processing system **500**, it may in some examples be at least partially external to data processing system **500**. Communications unit **510** may include internal and external technologies, e.g., modems (including regular telephone grade modems, cable modems, and DSL modems), ISDN adapters, and/or wired and wireless Ethernet cards, hubs, routers, etc. Data processing system **500** may operate in a networked environment, using logical connections to one or more remote computers **560**. A remote computer(s) **560** may include a personal computer (PC), a server, a router, a network PC, a workstation, a microprocessor-based appliance, a peer device, a smart phone, a tablet, another network note, and/or the like. Remote computer(s) **560** typically include many of the elements described relative to data processing system **500**. Remote computer(s) **560** may be logically connected to data processing system **500** through a network interface **562** which is connected to data processing system **500** via communications unit **510**. Network interface **562** encompasses wired and/or wireless communication networks, such as local-area networks (LAN), wide-area networks (WAN), and cellular networks. LAN technologies may include Fiber Distributed Data Interface (FDDI), Copper Distributed Data Interface (CDDI), Ethernet, Token Ring, and/or the like. WAN technologies include point-to-point links, circuit switching networks (e.g., Integrated Services Digital networks (ISDN) and variations thereon), packet switching networks, and Digital Subscriber Lines (DSL).

[0112] Codec **530** may include an encoder, a decoder, or both, comprising hardware, software, or a combination of hardware and software. Codec **530** may include any suitable device and/or software configured to encode, compress, and/or encrypt a data stream or signal for transmission and storage, and to decode the data stream or signal by decoding, decompressing, and/or decrypting the data stream or signal (e.g., for playback or editing of a video). Although codec **530** is depicted as a separate component, codec **530** may be contained or implemented in memory, e.g., non-volatile memory **542**.

[0113] Non-volatile memory **542** may include read only memory (ROM), programmable ROM (PROM), electrically programmable ROM (EPROM), electrically erasable programmable ROM (EEPROM), flash memory, and/or the like, or any combination of these. Volatile memory **540** may include random access memory (RAM), which may act as external cache memory. RAM may comprise static RAM (SRAM), dynamic RAM (DRAM), synchronous DRAM (SDRAM), double data rate SDRAM (DDR SDRAM), enhanced SDRAM (ESDRAM), and/or the like, or any combination of these.

[0114] Instructions for the operating system, applications, and/or programs may be located in storage devices **516**, which are in communication with processor unit **504** through system bus **502**. In these illustrative examples, the instructions are in a functional form in persistent storage **508**. These instructions may be loaded into memory **506** for execution by processor unit **504**. Processes of one or more embodiments of the present disclosure may be performed by

processor unit **504** using computer-implemented instructions, which may be located in a memory, such as memory **506**.

[0115] These instructions are referred to as program instructions, program code, computer usable program code, or computer-readable program code executed by a processor in processor unit **504**. The program code in the different embodiments may be embodied on different physical or computer-readable storage media, such as memory **506** or persistent storage **508**. Program code **518** may be located in a functional form on computer-readable media **520** that is selectively removable and may be loaded onto or transferred to data processing system **500** for execution by processor unit **504**. Program code **518** and computer-readable media **520** form computer program product **522** in these examples. In one example, computer-readable media **520** may comprise computer-readable storage media **524** or computer-readable signal media **526**.

[0116] Computer-readable storage media **524** may include, for example, an optical or magnetic disk that is inserted or placed into a drive or other device that is part of persistent storage **508** for transfer onto a storage device, such as a hard drive, that is part of persistent storage **508**. Computer-readable storage media **524** also may take the form of a persistent storage, such as a hard drive, a thumb drive, or a flash memory, that is connected to data processing system **500**. In some instances, computer-readable storage media **524** may not be removable from data processing system **500**.

[0117] In these examples, computer-readable storage media **524** is a non-transitory, physical or tangible storage device used to store program code **518** rather than a medium that propagates or transmits program code **518**. Computer-readable storage media **524** is also referred to as a computer-readable tangible storage device or a computer-readable physical storage device. In other words, computer-readable storage media **524** is media that can be touched by a person.

[0118] Alternatively, program code **518** may be transferred to data processing system **500**, e.g., remotely over a network, using computer-readable signal media **526**. Computer-readable signal media **526** may be, for example, a propagated data signal containing program code **518**. For example, computer-readable signal media **526** may be an electromagnetic signal, an optical signal, and/or any other suitable type of signal. These signals may be transmitted over communications links, such as wireless communications links, optical fiber cable, coaxial cable, a wire, and/or any other suitable type of communications link. In other words, the communications link and/or the connection may be physical or wireless in the illustrative examples.

[0119] In some illustrative embodiments, program code **518** may be downloaded over a network to persistent storage **508** from another device or data processing system through computer-readable signal media **526** for use within data processing system **500**. For instance, program code stored in a computer-readable storage medium in a server data processing system may be downloaded over a network from the server to data processing system **500**. The computer providing program code **518** may be a server computer, a client computer, or some other device capable of storing and transmitting program code **518**.

[0120] In some examples, program code **518** may comprise an operating system (OS) **550**. Operating system **550**, which may be stored on persistent storage **508**, controls and allocates resources of data processing system **500**. One or more applications **552** take advantage of the operating system's management of resources via program modules **554**, and program data **556** stored on storage devices **516**. OS **550** may include any suitable software system configured to manage and expose hardware resources of computer **500** for sharing and use by applications **552**. In some examples, OS **550** provides application programming interfaces (APIs) that facilitate connection of different type of hardware and/or provide applications **552** access to hardware and OS services. In some examples, certain applications **552** may provide further services for use by other applications **552**, e.g., as is the case with so-called "middleware." Aspects of present disclosure may be implemented with respect to various operating systems or combinations of operating systems.

[0121] The different components illustrated for data processing system **500** are not meant to provide architectural limitations to the manner in which different embodiments may be implemented. One or more embodiments of the present disclosure may be implemented in a data processing system that includes fewer components or includes components in addition to and/or in place of those illustrated for computer **500**. Other components shown in FIG. **11** can be varied from the examples depicted. Different embodiments may be implemented using any hardware device or system capable of running program code. As one example, data processing system **500** may include organic components integrated with inorganic components and/or may be comprised entirely of organic components (excluding a human being). For example, a storage device may be comprised of an organic semiconductor.

[0122] In some examples, processor unit **504** may take the form of a hardware unit having hardware circuits that are specifically manufactured or configured for a particular use, or to produce a particular outcome or progress. This type of hardware may perform operations without needing program code **518** to be loaded into a memory from a storage device to be configured to perform the operations. For example, processor unit **504** may be a circuit system, an application specific integrated circuit (ASIC), a programmable logic device, or some other suitable type of hardware configured (e.g., preconfigured or reconfigured) to perform a number of operations. With a programmable logic device, for example, the device is configured to perform the number of operations and may be reconfigured at a later time. Examples of programmable logic devices include, a programmable logic array, a field programmable logic array, a field programmable gate array (FPGA), and other suitable hardware devices. With this type of implementation, executable instructions (e.g., program code **518**) may be implemented as hardware, e.g., by specifying an FPGA configuration using a hardware description language (HDL) and then using a resulting binary file to (re)configure the FPGA.

[0123] In another example, data processing system **500** may be implemented as an FPGA-based (or in some cases ASIC-based), dedicated-purpose set of state machines (e.g., Finite State Machines (FSM)), which may allow critical tasks to be isolated and run on custom hardware. Whereas a processor such as a CPU can be described as a shared-use, general purpose state machine that executes instructions provided to it, FPGA-based state machine(s) are constructed for a special purpose, and may execute hardware-coded

logic without sharing resources. Such systems are often utilized for safety-related and mission-critical tasks.

[0124] In still another illustrative example, processor unit **504** may be implemented using a combination of processors found in computers and hardware units. Processor unit **504** may have a number of hardware units and a number of processors that are configured to run program code **518**. With this depicted example, some of the processes may be implemented in the number of hardware units, while other processes may be implemented in the number of processors.

[0125] In another example, system bus **502** may comprise one or more buses, such as a system bus or an input/output bus. Of course, the bus system may be implemented using any suitable type of architecture that provides for a transfer of data between different components or devices attached to the bus system. System bus **502** may include several types of bus structure(s) including memory bus or memory controller, a peripheral bus or external bus, and/or a local bus using any variety of available bus architectures (e.g., Industrial Standard Architecture (ISA), Micro-Channel Architecture (MSA), Extended ISA (EISA), Intelligent Drive Electronics (IDE), VESA Local Bus (VLB), Peripheral Component Interconnect (PCI), Card Bus, Universal Serial Bus (USB), Advanced Graphics Port (AGP), Personal Computer Memory Card International Association bus (PCMCIA), Firewire (IEEE 1394), and Small Computer Systems Interface (SCSI)).

[0126] Additionally, communications unit **510** may include a number of devices that transmit data, receive data, or both transmit and receive data. Communications unit **510** may be, for example, a modem or a network adapter, two network adapters, or some combination thereof. Further, a memory may be, for example, memory **506**, or a cache, such as that found in an interface and memory controller hub that may be present in system bus **502**.

D. Illustrative Distributed Data Processing System

[0127] As shown in FIG. **12**, this example describes a general network data processing system **600**, interchangeably termed a computer network, a network system, a distributed data processing system, or a distributed network, aspects of which may be included in one or more illustrative embodiments of the interactive system for guiding electronics design and assembly. For example, aspect of the electronics design aid may communicate with the distributed framework over a distributed network.

[0128] It should be appreciated that FIG. **12** is provided as an illustration of one implementation and is not intended to imply any limitation with regard to environments in which different embodiments may be implemented. Many modifications to the depicted environment may be made.

[0129] Network system **600** is a network of devices (e.g., computers), each of which may be an example of data processing system **500**, and other components. Network data processing system **600** may include network **602**, which is a medium configured to provide communications links between various devices and computers connected within network data processing system **600**. Network **602** may include connections such as wired or wireless communication links, fiber optic cables, and/or any other suitable medium for transmitting and/or communicating data between network devices, or any combination thereof.

[0130] In the depicted example, a first network device **604** and a second network device **606** connect to network **602**, as do one or more computer-readable memories or storage devices **608**. Network devices **604** and **606** are each examples of data processing system **500**, described above. In the depicted example, devices **604** and **606** are shown as server computers, which are in communication with one or more server data store(s) **622** that may be employed to store information local to server computers **604** and **606**, among others. However, network devices may include, without limitation, one or more personal computers, mobile computing devices such as personal digital assistants (PDAs), tablets, and smartphones, handheld gaming devices, wearable devices, tablet computers, routers, switches, voice gates, servers, electronic storage devices, imaging devices, media players, and/or other networked-enabled tools that may perform a mechanical or other function. These network devices may be interconnected through wired, wireless, optical, and other appropriate communication links.

[0131] In addition, client electronic devices **610** and **612** and/or a client smart device **614**, may connect to network **602**. Each of these devices is an example of data processing system **500**, described above regarding FIG. **11**. Client electronic devices **610**, **612**, and **614** may include, for example, one or more personal computers, network computers, and/or mobile computing devices such as personal digital assistants (PDAs), smart phones, handheld gaming devices, wearable devices, and/or tablet computers, and the like. In the depicted example, server **604** provides information, such as boot files, operating system images, and applications to one or more of client electronic devices **610**, **612**, and **614**. Client electronic devices **610**, **612**, and **614** may be referred to as "clients" in the context of their relationship to a server such as server computer **604**. Client devices may be in communication with one or more client data store(s) **620**, which may be employed to store information local to the clients (e,g., cookie(s) and/or associated contextual information). Network data processing system **600** may include more or fewer servers and/or clients (or no servers or clients), as well as other devices not shown.

[0132] In some examples, first client electric device **610** may transfer an encoded file to server **604**. Server **604** can store the file, decode the file, and/or transmit the file to second client electric device **612**. In some examples, first client electric device **610** may transfer an uncompressed file to server **604** and server **604** may compress the file. In some examples, server **604** may encode text, audio, and/or video information, and transmit the information via network **602** to one or more clients.

[0133] Client smart device **614** may include any suitable portable electronic device capable of wireless communications and execution of software, such as a smartphone or a tablet. Generally speaking, the term "smartphone" may describe any suitable portable electronic device configured to perform functions of a computer, typically having a touchscreen interface, Internet access, and an operating system capable of running downloaded applications. In addition to making phone calls (e.g., over a cellular network), smartphones may be capable of sending and receiving emails, texts, and multimedia messages, accessing the Internet, and/or functioning as a web browser. Smart devices (e.g., smartphones) may also include features of other known electronic devices, such as a media player, personal digital assistant, digital camera, video camera, and/or global positioning system. Smart devices (e.g., smartphones) may be capable of connecting with other smart devices, comput-

ers, or electronic devices wirelessly, such as through near field communications (NFC), BLUETOOTH®, WiFi, or mobile broadband networks. Wireless connectively may be established among smart devices, smartphones, computers, and/or other devices to form a mobile network where information can be exchanged.

[0134] Data and program code located in system **600** may be stored in or on a computer-readable storage medium, such as network-connected storage device **608** and/or a persistent storage **508** of one of the network computers, as described above, and may be downloaded to a data processing system or other device for use. For example, program code may be stored on a computer-readable storage medium on server computer **604** and downloaded to client **610** over network **602**, for use on client **610**. In some examples, client data store **620** and server data store **622** reside on one or more storage devices **608** and/or **508**.

[0135] Network data processing system **600** may be implemented as one or more of different types of networks. For example, system **600** may include an intranet, a local area network (LAN), a wide area network (WAN), or a personal area network (PAN). In some examples, network data processing system **600** includes the Internet, with network **602** representing a worldwide collection of networks and gateways that use the transmission control protocol/Internet protocol (TCP/IP) suite of protocols to communicate with one another. At the heart of the Internet is a backbone of high-speed data communication lines between major nodes or host computers.

[0136] Thousands of commercial, governmental, educational and other computer systems may be utilized to route data and messages. In some examples, network **602** may be referred to as a "cloud." In those examples, each server **604** may be referred to as a cloud computing node, and client electronic devices may be referred to as cloud consumers, or the like. FIG. **12** is intended as an example, and not as an architectural limitation for any illustrative embodiments.

E. Selected Embodiments and Claim Concepts

[0137] This section describes additional aspects and features of an interactive system for guiding electronics design and assembly, presented without limitation as a series of paragraphs, some or all of which may be alphanumerically designated for clarity and efficiency. Each of these paragraphs can be combined with one or more other paragraphs, and/or with disclosure from elsewhere in this application, including any attached Appendices, in any suitable manner. Some of the paragraphs below may expressly refer to and further limit other paragraphs, providing without limitation examples of some of the suitable combinations.

[0138] A0. A computer implemented method for electronics design, the method comprising:

[0139] receiving, via a graphical user interface (GUI), first information relating to a requested electronic circuit, the first information including a selected type of electronic circuit and one or more operating criteria relating to requested fundamental functionality of the selected type of electronic circuit;

[0140] receiving, via the GUI, second information relating to requested secondary attributes of a hypothetical candidate electronic circuit that satisfies the first information;

[0141] displaying, via the GUI, a set of candidate circuit architectures satisfying the first information, and a visualization of how each of the candidate circuit architectures relates to the second information;

[0142] receiving, via the GUI, a user selection from the set of candidate circuit architectures to define a selected circuit architecture; and

[0143] displaying, via the GUI, detailed information regarding the selected circuit architecture, including a simulation of electronic behavior of the selected circuit architecture and a listing of specific components included in the selected circuit architecture.

[0144] A1. The method of A0, further comprising:

[0145] receiving, via the GUI, at least one change to one of the specific components, and in response verifying whether the selected circuit architecture continues to satisfy the first information and the second information.

[0146] A2. The method of A0 or A1, further comprising:

[0147] receiving, via the GUI, at least one change to a physical layout of the selected circuit architecture, and in response verifying whether the selected circuit architecture continues to satisfy the first information and the second information.

[0148] A3. The method of any one of paragraphs A0 through A2, wherein the listing of specific components includes vendor-specific information relating to each of the specific components.

[0149] A4. The method of any one of paragraphs A0 through A3, wherein the one or more operating criteria relating to desired fundamental functionality include a specific voltage input and/or a specific voltage output.

[0150] A5. The method of any one of paragraphs A0 through A4, wherein the selected secondary attributes include a maximum operating temperature.

[0151] A6. The method of any one of paragraphs A0 through A5, wherein the selected secondary attributes include a maximum overall printed circuit board (PCB) dimension.

[0152] A7. The method of A6, wherein the overall PCB dimension is an area.

[0153] A8. The method of A6, wherein the overall PCB dimension is a height.

[0154] A9. The method of any one of paragraphs A0 through A8, wherein the visualization comprises:

[0155] one or more bar charts, each of the bar charts corresponding to a respective one of the secondary attributes, and each bar at a given relative position in each of the bar charts representing a corresponding value of the secondary attribute for a respective one of the candidate circuit architectures;

[0156] wherein each of the bar charts further includes a visual indication of a desired value for the corresponding secondary attribute, such that each bar chart shows a relative compliance of each of the candidate circuit architectures with the corresponding secondary attribute.

[0157] A10. The method of any one of paragraphs A0 through A9, further comprising ordering the specific components from respective vendors.

[0158] A11. The method of any one of paragraphs A0 through A10, further comprising displaying trust-related information relating to at least one of the specific components, the trust-related information being provided by a different user.

[0159] A12. The method of any one of paragraphs A0 through A11, wherein displaying detailed information

regarding the selected circuit architecture further includes simulating expected electronic behavior of the selected circuit architecture and displaying information relating to the simulated behavior.

[0160] B0. A data processing system for designing electronics, the system comprising:

[0161] one or more processors;

[0162] a memory; and

[0163] an electronics design program including a plurality of instructions stored in the memory and executable by the one or more processors to:

[0164] receive, via a graphical user interface (GUI), first information relating to a requested electronic circuit, the first information including a selected type of electronic circuit and one or more operating criteria relating to requested fundamental functionality of the selected type of electronic circuit;

[0165] receive, via the GUI, second information relating to requested secondary attributes of a hypothetical candidate electronic circuit that satisfies the first information;

[0166] display, via the GUI, a set of candidate circuit architectures satisfying the first information, and a visualization of how each of the candidate circuit architectures relates to the second information;

[0167] receive, via the GUI, a user selection from the set of candidate circuit architectures to define a selected circuit architecture; and

[0168] display, via the GUI, detailed information regarding the selected circuit architecture, including a simulation of electronic behavior of the selected circuit architecture and a listing of specific components included in the selected circuit architecture.

[0169] B1. The system of B0, wherein the plurality of instructions are further executable to:

[0170] receive, via the GUI, at least one change to one of the specific components, and in response verify whether the selected circuit architecture continues to satisfy the first information and the second information.

[0171] B2. The system of B0 or B1, wherein the plurality of instructions are further executable to:

[0172] receive, via the GUI, at least one change to a physical layout of the selected circuit architecture, and in response verify whether the selected circuit architecture continues to satisfy the first information and the second information.

[0173] B3. The system of any one of paragraphs B0 through B2, wherein the one or more operating criteria relating to desired fundamental functionality include a specific voltage input and/or a specific voltage output.

[0174] B4. The system of any one of paragraphs B0 through B3, wherein the selected secondary attributes include a maximum operating temperature.

[0175] B5. The system of any one of paragraphs B0 through B4, wherein the selected secondary attributes include a maximum overall printed circuit board (PCB) dimension.

[0176] B6. The system of any one of paragraphs B0 through B5, wherein displaying the visualization comprises:

[0177] presenting one or more bar charts, each of the bar charts corresponding to a respective one of the secondary attributes, and each bar at a given relative position in each of the bar charts representing a corresponding value of the secondary attribute for a respective one of the candidate circuit architectures;

[0178] wherein each of the bar charts further includes a visual indication of a desired value for the corresponding secondary attribute, such that each bar chart shows a relative compliance of each of the candidate circuit architectures with the corresponding secondary attribute.

[0179] B7. The system of any one of paragraphs B0 through B6, further comprising displaying trust-related information relating to at least one of the specific components, the trust-related information being provided by a different user.

[0180] C0. A data processing framework configured to host applications for designing electronics, the data process framework comprising:

[0181] a cloud system hosted on one or more remote servers, the cloud system including:

[0182] a memory including a central database comprising data on electronics components; and

[0183] a central AI module;

[0184] one or more data isolation nodes, each data isolation node distributed across a plurality of data processing systems, each data isolation node comprising:

[0185] a corporate AI module as described herein in network communication with a plurality of context AI modules as described herein, each context AI module hosted on a unique one of the plurality of data processing systems; and

[0186] a local database having a portion of the data from the central database;

[0187] wherein the cloud system and the one or more data isolation nodes are in network communication through a security filter.

[0188] C1. The data processing framework of paragraph C0, wherein the security filter comprises an end-to-end encryption algorithm.

[0189] C2. The data processing framework of any one of paragraphs C0 through C1 further comprising a trust AI module as described herein.

[0190] C3. The data processing framework of any one of paragraphs C0 through C2 further comprising a data processing system for designing electronics (i.e., a design aid) in accordance with any one of paragraphs B0 through B7 and/or implementing the method of any one of paragraphs A0 through A12, e.g., hosted on each computer in each data isolation node in communication with each context AI and the local database.

[0191] C4. The data processing framework of C3, wherein the corporate AI aggregates from each instance of the design aid.

Advantages, Features, and Benefits

[0192] The different embodiments and examples of the interactive system for guiding electronics design and assembly described herein provide several advantages over known solutions for guiding the design and assembly of electronics. For example, illustrative embodiments and examples described herein allow for easier and faster development of electronics.

[0193] Additionally, and among other benefits, illustrative embodiments and examples described herein include a useful and time-saving UI which provides a visualization of

candidate circuit architectures compared to desired attributes all in one place, and enables the user to compare and consider trade-offs between such desired attributes. This can produce a much-improved electronic design as compared with one strictly adhering to the originally entered attributes. No known user interfaces include this feature.

[0194] Additionally, and among other benefits, illustrative embodiments and examples described herein allow for real-time analysis of electronics having selectable components.

[0195] Additionally, and among other benefits, illustrative embodiments and examples described herein allow a comprehensive global analysis of the electronics industry.

[0196] Additionally, and among other benefits, illustrative embodiments and examples described herein allow a personalized design tool that adaptively learns from the user.

[0197] No known system or device can perform these functions. However, not all embodiments and examples described herein provide the same advantages or the same degree of advantage.

CONCLUSION

[0198] The disclosure set forth above may encompass multiple distinct examples with independent utility. Although each of these has been disclosed in its preferred form(s), the specific embodiments thereof as disclosed and illustrated herein are not to be considered in a limiting sense, because numerous variations are possible. To the extent that section headings are used within this disclosure, such headings are for organizational purposes only. The subject matter of the disclosure includes all novel and nonobvious combinations and subcombinations of the various elements, features, functions, and/or properties disclosed herein. The following claims particularly point out certain combinations and subcombinations regarded as novel and nonobvious. Other combinations and subcombinations of features, functions, elements, and/or properties may be claimed in applications claiming priority from this or a related application. Such claims, whether broader, narrower, equal, or different in scope to the original claims, also are regarded as included within the subject matter of the present disclosure.

1. A computer implemented method for electronics design, the method comprising:

receiving, via a graphical user interface (GUI), first information including a selected type of electronic circuit assembly and one or more criteria relating to the selected type of electronic circuit assembly;

for each one of a plurality of subtypes of the selected type of electronic circuit assembly: simultaneously displaying, via the GUI, a plurality of circuit assemblies satisfying the first information, wherein each of the circuit assemblies comprises a respective configuration of circuit components, and a plurality of graphical visualizations, each of the plurality of graphical visualizations displaying how each of the plurality of circuit assemblies relates to the one or more criteria;

receiving, via the GUI, a user selection from the plurality of circuit assemblies to define a selected circuit assembly; and

displaying, via the GUI, detailed information regarding the selected circuit assembly, including a listing of specific components included in the selected circuit assembly.

2. The method of claim **1**, wherein displaying detailed information regarding the selected circuit assembly further includes simulating expected electronic behavior of the selected circuit assembly and displaying information relating to the simulated behavior.

3. The method of claim **1**, further comprising:

receiving, via the GUI, at least one change to one of the specific components, and in response verifying whether the selected circuit assembly continues to satisfy the first information.

4. The method of claim **1**, further comprising:

receiving, via the GUI, at least one change to a physical layout of the selected circuit assembly, and in response verifying whether the selected circuit assembly continues to satisfy the first information.

5. The method of claim **1**, wherein the listing of specific components includes vendor-specific information relating to each of the specific components.

6. The method of claim **1**, wherein at least one of the one or more criteria comprises operating criteria relating to fundamental functionality of the selected type of electronic circuit assembly.

7. The method of claim **6**, wherein the one or more operating criteria include a specific voltage input and/or a specific voltage output.

8. The method of claim **6**, wherein the one or more operating criteria include a maximum operating temperature.

9. The method of claim **6**, wherein at least one of the one or more criteria comprises one or more secondary attributes of the selected type of electronic circuit assembly.

10. The method of claim **9**, wherein the one or more secondary attributes include a maximum overall printed circuit board (PCB) dimension.

11. The method of claim **1**, wherein the plurality of graphical visualizations comprises:

one or more bar charts, each of the bar charts corresponding to a respective one of the criteria, and each bar at a given relative position in each of the bar charts representing a corresponding value of the criteria for a respective one of the plurality of circuit assemblies;

wherein each of the bar charts further includes a visual indication of a desired value for the respective one of the criteria.

12. The method of claim **1**, further comprising ordering the specific components from respective vendors.

13. The method of claim **1**, further comprising displaying trust-related information relating to at least one of the specific components, the trust-related information being provided by a different user.

14. A data processing system for designing electronics, the system comprising:

one or more processors;

a memory; and

an electronics design program including a plurality of instructions stored in the memory and executable by the one or more processors to:

receive, via a graphical user interface (GUI), first information including a selected type of electronic circuit assembly and one or more criteria relating to the selected type of electronic circuit;

for each one of a plurality of subtypes of the selected type: simultaneously display, via the GUI, a set of circuit assemblies satisfying the first information, wherein each of the circuit assemblies comprises a respective configuration of circuit components, and a

plurality of graphical visualizations, each of the plurality of graphical visualizations corresponding to how each of the circuit assemblies relates to the one or more criteria;

receive, via the GUI, a user selection from the set of circuit assemblies to define a selected circuit assembly; and

display, via the GUI, detailed information regarding the selected circuit assembly, including a simulation of electronic behavior of the selected circuit assembly and a listing of specific components included in the selected circuit assembly.

15. The system of claim **14**, wherein the plurality of instructions are further executable to:

receive, via the GUI, at least one change to one of the specific components, and in response verify whether the selected circuit assembly continues to satisfy the first information.

16. The system of claim **14**, wherein the plurality of instructions are further executable to:

receive, via the GUI, at least one change to a physical layout of the selected circuit assembly, and in response verify whether the selected circuit assembly continues to satisfy the first information.

17. The system of claim **14**, wherein the one or more criteria include a specific voltage input and/or a specific voltage output.

18. The system of claim **14**, wherein the first information further includes a maximum overall printed circuit board (PCB) dimension.

19. The system of claim **14**, wherein displaying the plurality of graphical visualizations comprises:

presenting one or more bar charts, each of the bar charts corresponding to a respective one of the criteria, and each bar at a given relative position in each of the bar charts representing a corresponding value of the criteria for a respective one of the set of circuit assemblies;

wherein each of the bar charts further includes a visual indication of a desired value for the respective criteria.

20. The system of claim **14**, wherein the plurality of instructions are further executable to:

simulate expected electronic behavior of the selected circuit assembly and display information relating to the simulated behavior on the GUI.

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